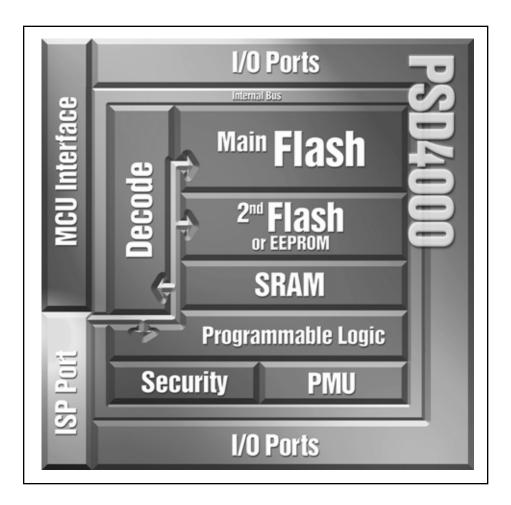


PSD4000 Series PSD4135G2 Flash In-System-Programmable Peripherals for 16-Bit MCUs

May, 2000 Beta Information



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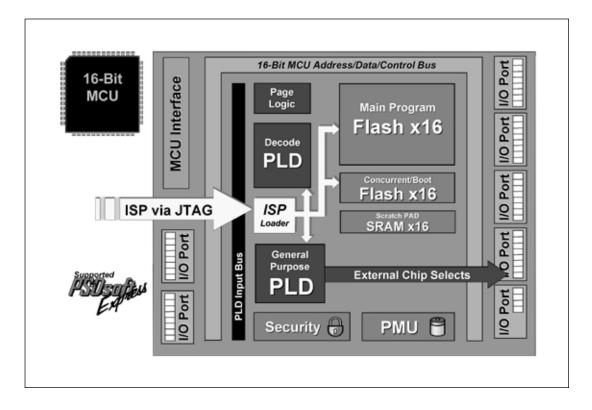
PSD4000 Series PSD4135G2 Configurable Memory System on a Chip for 16-Bit Microcontrollers

Beta Site Information

1.0 Introduction

The PSD4000 series of Programmable Microcontroller (MCU) Peripherals brings In-System-Programmability (ISP) to Flash memory and programmable logic. The result is a simple and flexible solution for embedded designs. PSD4000 devices combine many of the peripheral functions found in MCU based applications:

- 4 Mbit of Flash memory
- A secondary Flash memory for boot or data
- Over 3,000 gates of Flash programmable logic
- 64 Kbit SRAM
- Reconfigurable I/O ports
- Programmable power management.



1.0 Introduction (Cont.)

The PSD4135G2 device offers two methods to program PSD Flash memory while the PSD is soldered to a circuit board.

□ In-System Programming (ISP) via JTAG

An IEEE 1149.1 compliant JTAG-ISP interface is included on the PSD enabling the entire device (both flash memories, the PLD, and all configuration) to be rapidly programmed while soldered to the circuit board. This requires no MCU participation, which means the PSD can be programmed anytime, even while completely blank.

The innovative JTAG interface to flash memories is an industry first, solving key problems faced by designers and manufacturing houses, such as:

- First time programming How do I get firmware into the flash the very first time? JTAG is the answer, program the PSD while blank with no MCU involvement.
- Inventory build-up of pre-programmed devices How do I maintain an accurate count of pre-programmed flash memory and PLD devices based on customer demand? How many and what version? JTAG is the answer, build your hardware with blank PSDs soldered directly to the board and then custom program just before they are shipped to customer. No more labels on chips and no more wasted inventory.
- Expensive sockets How do I eliminate the need for expensive and unreliable sockets? JTAG is the answer. Solder the PSD directly to the circuit board. Program first time and subsequent times with JTAG. No need to handle devices and bend the fragile leads.

□ In-Application re-Programming (IAP)

Two independent flash memory arrays are included so the MCU can execute code from one memory while erasing and programming the other. Robust product firmware updates in the field are possible over any communication channel (CAN, Ethernet, UART, J1850, etc) using this unique architecture. Designers are relieved of these problems:

- Simultaneous read and write to flash memory How can the MCU program the same memory from which it is executing code? It cannot. The PSD allows the MCU to operate the two flash memories concurrently, reading code from one while erasing and programming the other during IAP.
- **Complex memory mapping** How can I map these two memories efficiently? A Programmable Decode PLD is embedded in the PSD. The concurrent PSD memories can be mapped anywhere in MCU address space, segment by segment with extremely high address resolution. As an option, the secondary flash memory can be swapped out of the system memory map when IAP is complete. A built-in page register breaks the MCU address limit.
- Separate program and data space How can I write to flash memory while it resides in "program" space during field firmware updates, my 80C51XA won't allow it! The flash PSD provides means to "reclassify" flash memory as "data" space during IAP, then back to "program" space when complete.

PSDsoft – Waferscale's software development tool – guides you through the design process step-by-step making it possible to complete an embedded MCU design capable of ISP/IAP in just hours. Select your MCU and PSDsoft will take you through the remainder of the design with point and click entry, covering...PSD selection, pin definitions, programmable logic inputs and outputs, MCU memory map definition, ANSI C code generation for your MCU, and merging your MCU firmware with the PSD design. When complete, two different device programmers are supported directly from PSDsoft – FlashLINK (JTAG) and PSDpro.

The PSD4135G2 is available in an 80-pin TQFP package.

Please refer to the revision block at the end of this document for updated information.



2.0 Key Features	 A simple interface to 16-bit microcontrollers that use either multiplexed or non-multiplexed busses. The bus interface logic uses the control signals generated by the microcontroller automatically when the address is decoded and a read or write is performed. A partial list of the MCU families supported include: Intel 80196, 80296, 80186, and 80386EX Motorola 68HC16, 68HC12, 683XX, and MC2001 Philips 80C51XA
	Infineon C16X devicesHitachi H8
	4 Mbit Flash memory. This is the main Flash memory. It is divided into eight equal-sized blocks that can be accessed with user-specified addresses.
	Internal secondary 256 Kbit Flash boot memory. It is divided into four equal-sized blocks that can be accessed with user-specified addresses. This secondary memory brings the ability to execute code and update the main Flash concurrently.
	64 Kbit SRAM. The SRAM's contents can be protected from a power failure by connecting an external battery.
	General Purpose PLD (GPLD) with 24 outputs. The GPLD may be used to implement external chip selects or combinatorial logic function.
	Decode PLD (DPLD) that decodes address for selection of internal memory blocks.
	 52 individually configurable I/O port pins that can be used for the following functions: MCU I/Os PLD I/Os Latched MCU address output Special function I/Os. I/O ports may be configured as open-drain outputs.
	Standby current as low as 50 μA for 5 V devices.
	Built-in JTAG compliant serial port allows full-chip In-System Programmability (ISP). With it, you can program a blank device or reprogram a device in the factory or the field
	Internal page register that can be used to expand the microcontroller address space by a factor of 256.
	Internal programmable Power Management Unit (PMU) that supports a low power mode called Power Down Mode. The PMU can automatically detect a lack of microcontroller activity and put the PSD4000 into Power Down Mode.
	 Erase/Write cycles: Elash memory – 100 000 minimum

- Flash memory 100,000 minimum
 PLD 1,000 minimum
- 15 year data retention

3.0 PSD4000 **Series**

Part # PSD4000 Series	Device	I/O Pins	PLD Inputs	Input Macrocells	Output Macrocells	PLD Outputs	Flash Serial ISP JTAG/ISP Port	Flash Main Memory Kbit 8 Sectors	Boot Memory Kbit (4 Sectors)	SRAM Kbit	Supply Voltage	
PSD4000	PSD4135G2	52	66			24	Yes	4096	256	64	5V	
	PSD4235G2*	52	82	24	16	24	Yes	4096	256	64	5V	

Table 1, PSD4000 Product Matrix

*See PSD4235G2 Data Sheet.



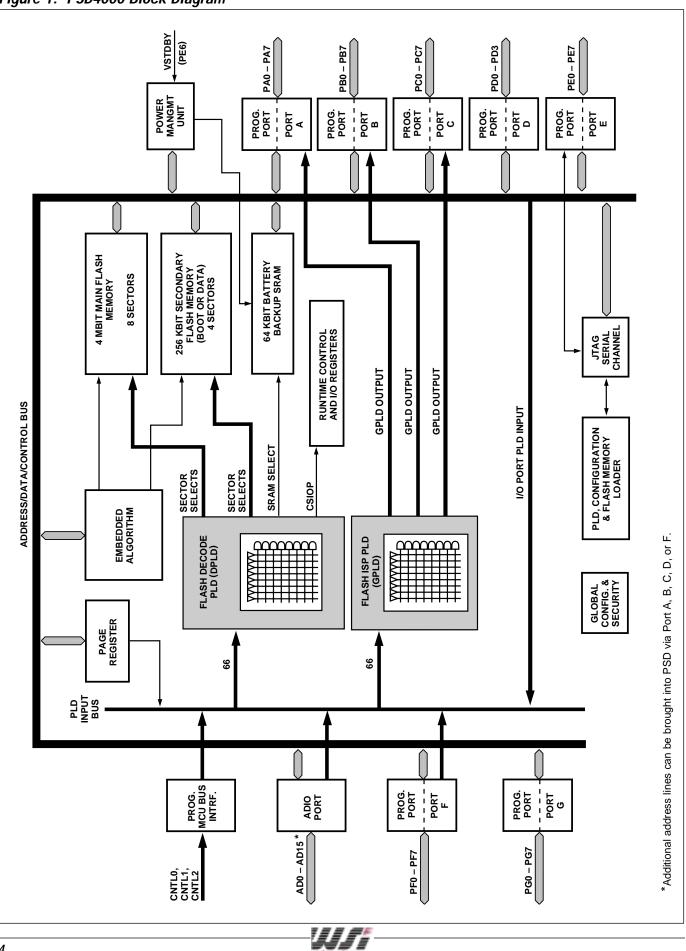


Figure 1. PSD4000 Block Diagram

4.0 PSD4000 Architectural Overview

PSD4000 devices contain several major functional blocks. Figure 1 on page 3 shows the architecture of the PSD4000 device family. The functions of each block are described briefly in the following sections. Many of the blocks perform multiple functions and are user configurable.

4.1 Memory

The PSD4000 contains the following memories:

- 4 Mbit Flash
- A secondary 256 Kbit Flash memory for boot or data
- 64 Kbit SRAM.

Each of the memories is briefly discussed in the following paragraphs. A more detailed discussion can be found in section 9.

The 4 Mbit Flash is the main memory of the PSD4000. It is divided into eight equally-sized sectors that are individually selectable.

The 256 Kbit secondary Flash memory is divided into four equally-sized sectors. Each sector is individually selectable.

The 64 Kbit SRAM is intended for use as a scratchpad memory or as an extension to the microcontroller SRAM. If an external battery is connected to the PSD4000's Vstby pin, data will be retained in the event of a power failure.

Each block of memory can be located in a different address space as defined by the user. The access times for all memory types includes the address latching and DPLD decoding time.

4.2 PLDs

The device contains two PLD blocks, each optimized for a different function, as shown in Table 2. The functional partitioning of the PLDs reduces power consumption, optimizes cost/performance, and eases design entry.

The Decode PLD (DPLD) is used to decode addresses and generate chip selects for the PSD4000 internal memory and registers. The General Purpose PLD (GPLD) can implement user-defined external chip selects and logic functions. The PLDs receive their inputs from the PLD Input Bus and are differentiated by their output destinations, number of Product Terms.

The PLDs consume minimal power by using Zero-Power design techniques. The speed and power consumption of the PLD is controlled by the Turbo Bit in the PMMR0 register and other bits in the PMMR2 registers. These registers are set by the microcontroller at runtime. There is a slight penalty to PLD propagation time when invoking the non-Turbo bit.

4.3 I/O Ports

The PSD4000 has 52 I/O pins divided among seven ports (Port A, B, C, D, E, F and G). Each I/O pin can be individually configured for different functions. Ports can be configured as standard MCU I/O ports, PLD I/O, or latched address outputs for microcontrollers using multiplexed address/data busses.

The JTAG pins can be enabled on Port E for In-System Programming (ISP). Ports F and G can also be configured as a data port for a non-multiplexed bus.

4.4 Microcontroller Bus Interface

The PSD4000 easily interfaces with most 16-bit microcontrollers that have either multiplexed or non-multiplexed address/data busses. The device is configured to respond to the microcontroller's control signals, which are also used as inputs to the PLDs. Section 9.3.5 contains microcontroller interface examples.

Table 2. PLD I/O Table

Name	Abbreviation	Inputs	Outputs	Product Terms
Decode PLD	DPLD	66	14	40
General PLD	GPLD	66	24	136



PSD4000 Architectural Overview (cont.)

4.5 ISP via JTAG Port

In-System Programming can be performed through the JTAG pins on Port E. This serial interface allows complete programming of the entire PSD4000 device. A blank device can be completely programmed. The JTAG signals (TMS, TCK, TSTAT, TERR, TDI, TDO) can be multiplexed with other functions on Port E. Table 3 indicates the JTAG signals pin assignments.

4.6 In-System Programming (ISP)

Using the JTAG signals on Port E, the entire PSD4000 (memory, logic, configuration) device can be programmed or erased without the use of the microcontroller.

Port E Pins	JTAG Signal
PE0	TMS
PE1	ТСК
PE2	TDI
PE3	TDO
PE4	TSTAT
PE5	TERR

4.7 In-Application re-Programming (IAP)

The main Flash memory can also be programmed in-system by the microcontroller executing the programming algorithms out of the secondary Flash memory, or SRAM. Since this is a sizable separate block, the application can also continue to operate. The secondary Flash boot memory can be programmed the same way by executing out of the main Flash memory. Table 4 indicates which programming methods can program different functional blocks of the PSD4000.

Functional Block	JTAG-ISP	Device Programmer	IAP
Main Flash memory	Yes	Yes	Yes
Flash Boot memory	Yes	Yes	Yes
PLD Array (DPLD and GPLD)	Yes	Yes	No
PSD Configuration	Yes	Yes	No

Table 4. Methods of Programming Different Functional Blocks of the PSD4000

4.8 Page Register

The eight-bit Page Register expands the address range of the microcontroller by up to 256 times. The paged address can be used as part of the address space to access external memory and peripherals or internal memory and I/O. The Page Register can also be used to change the address mapping of blocks of Flash memory into different memory spaces for IAP.

4.9 Power Management Unit

The Power Management Unit (PMU) in the PSD4000 gives the user control of the power consumption on selected functional blocks based on system requirements. The PMU includes an Automatic Power Down unit (APD) that will turn off device functions due to microcontroller inactivity. The APD unit has a Power Down Mode that helps reduce power consumption.

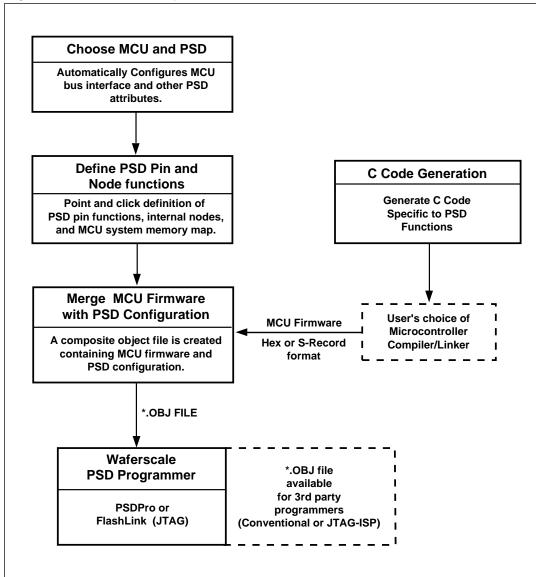
The PSD4000 also has some bits that are configured at run-time by the MCU to reduce power consumption of the GPLD. The turbo bit in the PMMR0 register can be turned off and the GPLD will latch its outputs and go to standby until the next transition on its inputs. Additionally, bits in the PMMR2 register can be set by the MCU to block signals from entering the GPLD to reduce power consumption. See section 9.5.



5.0 Development System

The PSD4000 series is supported by PSDsoft a Windows-based (95, 98, NT) software development tool. A PSD design is quickly and easily produced in a point and click environment. The designer does not need to enter Hardware Definition Language (HDL) equations (unless desired) to define PSD pin functions and memory map information. The general design flow is shown in Figure 2 below. PSDsoft is available from our web site (www.waferscale.com) or other distribution channels.

PSDsoft directly supports two low cost device programmers from Waferscale, PSDpro and FlashLINK (JTAG). Both of these programmers may be purchased through your local rep/distributor, or directly from our web site using a credit card. The PSD4000 is also supported by third party device programmers, see web site for current list.







6.0 Table 5. PSD4000 Pin Descriptions

The following table describes the pin names and pin functions of the PSD4000. Pins that have multiple names and/or functions are defined using PSDsoft.

Pin Name	Pin* (TQFP Pkg.)	Туре	Description
ADIO0-7	3-7 10-12	I/O	 This is the lower Address/Data port. Connect your MCU address or address/data bus according to the following rules: 1. If your MCU has a multiplexed address/data bus where the data is multiplexed with the lower address bits, connect AD[0:7] to this port. 2. If your MCU does not have a multiplexed address/data bus, connect A[0:7] to this port. 3. If you are using an 80C51XA in burst mode, connect A4/D0 through A11/D7 to this port. ALE or AS latches the address. The PSD drives data out only if the read signal is active and one of the PSD functional blocks was selected. The addresses on this port are passed to the PLDs.
ADIO8-15	13-20	I/O	 This is the upper Address/Data port. Connect your MCU address or address/data bus according to the following rules: 1. If your MCU has a multiplexed address/data bus where the data is multiplexed with the upper address bits, connect AD[8:15] to this port. 2. If your MCU does not have a multiplexed address/data bus, connect A[8:15] to this port. 3. If you are using an 80C51XA in burst mode, connect A12/D8 through A19/D15 to this port. ALE or AS latches the address. The PSD drives data out only if the read signal is active and one of the PSD functional blocks was selected. The addresses on this port are passed to the PLDs.
CNTL0	59	I	 The following control signals can be connected to this port, based on your MCU: 1. WR — active-low write input. 2. <u>R_W</u> — active-high read/active low write input. 3. WRL — Write to low byte, active low This pin is connected to the PLDs. Therefore, these signals can be used in decode and other logic equations.
CNTL1	60	I	 The following control signals can be connected to this port, based on your MCU: 1. RD — active-low read input. 2. E — E clock input. 3. DS — active-low data strobe input. 4. LDS — Strobe for low data byte, active low. This pin is connected to the PLDs. Therefore, these signals can be used in decode and other logic equations.
CNTL2	40	1	 Read or other Control input pin with multiple configurations. Depending on the MCU interface selected, this pin can be: 1. PSEN — Program Select enable, active low in code fetch bus cycle (80C51XA mode) 2. BHE — High byte enable. 3. UDS — Strobe for high data byte, 16-bit data bus mode, active low. 4. SIZ0 — Byte enable input. 5. LSTRB — Low strobe input. This pin is also connected to PLD as input.



Table 5.		Din *		
PSD4000		Pin* (TQFP		
Pin	Pin Name		Туре	Description
Descriptions (cont.)	Reset	39	I	Active low input. Resets I/O Ports, PLD Micro⇔Cells, some of the configuration registers and JTAG registers. Must be active at power up. Reset also aborts the Flash programming/erase cycle that is in progress.
	PA0-PA7	51-58	I/O CMOS or Open Drain	 Port A, PA0-7. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port 2. GPLD output. 3. Input to the PLD (can also be PLD input for address A16 and above).
	PB0-PB7	61-68	I/O CMOS or Open Drain	 Port B, PB0-7. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. GPLD output. 3. Input to the PLD (can also be PLD input for address A16 and above).
	PC0-PC7	41-48	I/O CMOS or Slew Rate	 Port C, PC0-7. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. External chip select (ECS0-7) output. 3. Input to the PLD (can also be PLD input for address A16 and above).
	PD0	79	I/O CMOS or Open Drain	 Port D pin PD0 can be configured as: 1. <u>ALE</u> or AS input — latches addresses on ADIO0-15 pins 2. AS input — latches addresses on ADIO0-15 pins on the rising edge. 3. Input to the PLD (can also be PLD input for address A16 and above).
	PD1	80	I/O CMOS or Open Drain	 Port D pin PD1 can be configured as: 1. MCU I/O 2. Input to the PLD (can also be PLD input for address A16 and above). 3. CLKIN clock input — clock input to the GPLD Micro⇔Cells, the APD power down counter and GPLD AND Array.
	PD2	1	I/O CMOS or Open Drain	 Port D pin PD2 can be configured as: 1. MCU I/O 2. Input to the PLD (can also be PLD input for address A16 and above). 3. CSI input — chip select input. When low, the CSI enables the internal PSD memories and I/O. When high, the internal memories are disabled to conserve power. CSI trailing edge can get the part out of power-down mode.
	PD3	2	I/O CMOS or Open Drain	 Port D pin PD3 can be configured as: 1. MCU I/O 2. Input to the PLD (can also be PLD input for address A16 <u>and above</u>). 3. WRH — for 16-bit data bus, write to high byte, active low.
	PE0	71	I/O CMOS or Open Drain	 Port E, PE0. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address output. 3. TMS input for JTAG/ISP interface.



<i>Table 5. PSD4000 Pin</i>	Pin Name	Pin* (TQFP Pkg.)	Туре	Description
Descriptions (cont.)	PE1	72	I/O CMOS or Open Drain	 Port E, PE1. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address output. 3. TCK input for JTAG/ISP interface (Schmidt Trigger).
	PE2	73	I/O CMOS or Open Drain	 Port E, PE2. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address output. 3. TDI input for JTAG/ISP interface.
	PE3	74	I/O CMOS or Open Drain	 Port E, PE3. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address output. 3. TDO output for JTAG/ISP interface.
	PE4	75	I/O CMOS or Open Drain	 Port E, PE4. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address output. 3. TSTAT output for the ISP interface. 4. Rdy/Bsy — for in-circuit Parallel Programming.
	PE5	76	I/O CMOS or Open Drain	 Port E, PE5. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. <u>Latch</u>ed address output. 3. TERR active low output for ISP interface.
	PE6	77	I/O CMOS or Open Drain	 Port E, PE6. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address output. 3. Vstby — SRAM standby voltage input for battery backup SRAM
	PE7	78	I/O CMOS or Open Drain	 Port E, PE7. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address output. 3. Vbaton — battery backup indicator output. Goes high when power is drawn from an external battery.
	PF0-PF7	31-38	I/O CMOS or Open Drain	 Port F, PF0-7. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Input to the PLD. 3. Latched address outputs. 4. As address A1-3 inputs in 80C51XA mode (PF0 is grounded) 5. As data bus port (D0-7) in non-multiplexed bus configuration 6. MCU reset mode.
	PG0-PG7	21-28	I/O CMOS or Open Drain	 Port G, PG0-7. This port is pin configurable and has multiple functions: 1. MCU I/O — standard output or input port. 2. Latched address outputs. 3. As data bus port (D8-15) in non-multiplexed bus configuration. 4. MCU reset mode.
	GND	8,30, 49,50, 70		
	V _{CC}	9,29, 69		



7.0 PSD4000 Register Description and Address Offset

Table 6 shows the offset addresses to the PSD4000 registers relative to the CSIOP base address. The CSIOP space is the 256 bytes of address that is allocated by the user to the internal PSD4000 registers. Table 6 provides brief descriptions of the registers in CSIOP space. For a more detailed description, refer to section 9.

Register Name	Port A	Port B	Port C	Port D	Port E	Port F	Port G	Other*	Description
Data In	00	01	10	11	30	40	41		Reads Port pin as input, MCU I/O input mode
Control					32	42	43		Selects mode between MCU I/O or Address Out
Data Out	04	05	14	15	34	44	45		Stores data for output to Port pins, MCU I/O output mode
Direction	06	07	16	17	36	46	47		Configures Port pin as input or output
Drive Select	08	09	18	19	38	48	49		Configures Port pins as either CMOS or Open Drain on some pins, while selecting high slew rate on other pins.
Flash Protection								C0	Read only – Flash Sector Protection
Flash Boot Protection								C2	Read only – PSD Security and Flash Boot Sector Protection
PMMR0								B0	Power Management Register 0
PMMR2								B4	Power Management Register 2
Page								E0	Page Register
VM								E2	Places PSD memory areas in Program and/or Data space on an individual basis.
Memory_ID0								F0	Read only – Flash and SRAM size
Memory_ID1								F1	Read only – Boot type and size

Table 6. Register Address Offset



8.0 Register Bit Definition

All the registers in the PSD4000 are included here for reference. Detail description of the registers are found in the Functional Block section of the Data Sheet.

Data In Registers – Port A, B, C, D, E, F and G

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Port Pin 7	Port Pin 6	Port Pin 5	Port Pin 4	Port Pin 3	Port Pin 2	Port Pin 1	Port Pin 0

Bit definitions:

Read only registers, read Port pin status when Port is in MCU I/O input Mode.

Data Out Registers – Port A, B, C, D, E, F and G

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Port Pin 7	Port Pin 6	Port Pin 5	Port Pin 4	Port Pin 3	Port Pin 2	Port Pin 1	Port Pin 0

Bit definitions:

Latched data for output to Port pin when pin is configured in MCU I/O output mode.

Direction Registers – Port A, B, C, D, E, F and G

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Port Pin 7	Port Pin 6	Port Pin 5	Port Pin 4	Port Pin 3	Port Pin 2	Port Pin 1	Port Pin 0

Bit definitions:

Set Register Bit to 0 = configure corresponding Port pin in Input mode (default).Set Register Bit to 1 = configure corresponding Port pin in Output mode.

Control Registers – Ports E, F and G

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Port Pin 7	Port Pin 6	Port Pin 5	Port Pin 4	Port Pin 3	Port Pin 2	Port Pin 1	Port Pin 0

Bit definitions:

Set Register Bit to 0 = configure corresponding Port pin in MCU I/O mode (default). Set Register Bit to 1 = configure corresponding Port pin in Latched Address Out mode.

Drive Registers – Ports A, B, D, E, and G

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Port Pin 7	Port Pin 6	Port Pin 5	Port Pin 4	Port Pin 3	Port Pin 2	Port Pin 1	Port Pin 0

Bit definitions:

Set Register Bit to 0 = configure corresponding Port pin in CMOS output driver (default).Set Register Bit to 1 = configure corresponding Port pin in Open Drain output driver.

Drive Registers – Ports C and F

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Port Pin 7	Port Pin 6	Port Pin 5	Port Pin 4	Port Pin 3	Port Pin 2	Port Pin 1	Port Pin 0

Bit definitions:

Set Register Bit to 0 = configure corresponding Port pin as CMOS output driver (default).Set Register Bit to 1 = configure corresponding Port pin in Slew Rate mode.

Flash Protection Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Sec7_Prot	Sec6_Prot	Sec5_Prot	Sec4_Prot	Sec3_Prot	Sec2_Prot	Sec1_Prot	Sec0_Prot

Bit definitions: Read Only Register

Sec<i>_Prot 1 = Flash Sector <i> is write protected.

Sec<i>_Prot 0 = Flash Sector <i> is not write protected.



8.0 **Register Bit** Definition (cont.)

- 1			-					
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	Security_Bit	*	*	*	Sec3_Prot	Sec2_Prot	Sec1_Prot	Sec0_Prot

Bit definitions:

Sec <i>_Prot</i>	1 = Boot Block Sector <i> is write protected.</i>
Sec <i>_Prot</i>	0 = Boot Block Sector <i> is not write protected.</i>
Security Bit	0 = Security Bit in device has not been set.

0 = Security Bit in device has not been set.

1 = Security Bit in device has been set.

Page Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Pgr7	Pgr6	Pgr5	Pgr4	Pgr3	Pgr2	Pgr1	Pgr0

Bit definitions:

Configure Page input to PLD. Default Pgr[7:0] = 00.

PMMR0 Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
*	*	PLD	PLD	PLD	*	APD	*
		Mcells clk	array-clk	Turbo		enable	

*Not used bit should be set to zero.

Bit definitions: (default is 0)

- Bit 1 0 = Automatic Power Down (APD) is disabled.
 - 1 = Automatic Power Down (APD) is enabled.
- Bit 3 0 = PLD Turbo is on.
 - 1 = PLD Turbo is off, saving power.
- Bit 4 0 = CLKIN input to the PLD AND array is connected.
 - Every CLKIN change will power up the PLD when Turbo bit is off.
 - 1 = CLKIN input to PLD AND array is disconnected, saving power.
- Bit 5 0 = CLKIN input to the PLD Micro \Leftrightarrow Cells is connected.
 - 1 = CLKIN input to the PLD Micro⇔Cells is disconnected, saving power.

PMMR2 Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
*	PLD	PLD	PLD	PLD	PLD	*	*
	array WRh	array Ale	array Cntl2	array Cntl1	array Cntl0		

*Not used bit should be set to zero.

Bit definitions (defauld is 0):

- Bit 0 0 =Address A[7:0] are connected into the PLD array.
 - 1 = Address A[7:0] are blocked from the PLD array, saving power. Note: in XA mode, A3-0 come from PF3-0 and A7-4 come from ADIO7-4.
- Bit 2 0 = Cntl0 input to the PLD AND array is connected.
 - 1 = Cntl0 input to the PLD AND array is disconnected, saving power.
- Bit 3 0 = Cntl1 input to the PLD AND array is connected.
 - 1 = Cntl1 input to the PLD AND array is disconnected, saving power.
- Bit 4 0 = Cntl2 input to the PLD AND array is connected.
 - 1 = Cntl2 input to the PLD AND array is disconnected, saving power.
- Bit 5 0 = Ale input to the PLD AND array is connected.
 - 1 = Ale input to the PLD AND array is disconnected, saving power.
- Bit 6 0 = WRh/DBE input to the PLD AND array is connected.
 - 1 = WRh/DBE input to the PLD AND array is disconnected, saving power.



8.0 Register Bit Definition

(cont.)

VM Register Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 * * * FL_data Boot_data FL_code Boot_code SR_code

Note: Upon reset, Bit1-Bit4 are loaded to configurations selected by the user in PSDsoft. Bit 0 is always cleared by reset. Bit 0 to Bit 4 are active only when the device is configured in Philips 80C51XA mode. Not used bit should be set to zero.

Bit definitions:

- Bit 0 $0 = \overline{PSEN}$ can't access SRAM in 80C51XA modes. 1 = \overline{PSEN} can access SRAM in 80C51XA modes.
- Bit 1 $0 = \overline{PSEN}$ can't access Boot in 80C51XA modes. 1 = PSEN can access Boot in 80C51XA modes.
- Bit 2 $0 = \overline{PSEN}$ can't access main Flash in 80C51XA modes. 1 = \overline{PSEN} can access main Flash in 80C51XA modes.
- Bit 3 $0 = \overline{RD}$ can't access Boot in 80C51XA modes. 1 = \overline{RD} can access Boot in 80C51XA modes.
- Bit 4 $0 = \overline{RD}$ can't access main Flash in 80C51XA modes. 1 = RD can access main Flash in 80C51XA modes.

Memory_ID0 Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
S_size 3	S_size 2	S_size 1	S_size 0	F_size 3	F_size 2	F_size 1	F_size 0

Bit definitions:

F_size[3:0] = 4h, main Flash size is 2M bit.

F_size[3:0] = 5h, main Flash size is 8M bit.

 $S_size[3:0] = 0h$, SRAM size is 0K bit.

S_size[3:0] = 1h, SRAM size is 16K bit.

 $S_size[3:0] = 3h$, SRAM size is 64K bit.

Memory_ID1 Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
*	*	B_type 1	B_type 0	B_size 3	B_size 2	B_size 1	B_size 0

*Not used bit should be set to zero.

Bit definitions:

B_size[3:0] = 0h, Boot block size is 0K bit.

B_size[3:0] = 2h, Boot block size is 256K bit.

B_type[1:0] = 0h, Boot block is Flash memory.

9.0 The PSD4000 Functional Blocks

As shown in Figure 1, the PSD4000 consists of six major types of functional blocks:

Memory Blocks

- PLD Blocks
- Bus Interface
- I/0 Ports
- Power Management Unit
- JTAG-ISP Interface

The functions of each block are described in the following sections. Many of the blocks perform multiple functions, and are user configurable.

9.1 Memory Blocks

The PSD4000 has the following memory blocks:

- The main Flash memory
- Secondary Flash memory
- SRAM.

The memory select signals for these blocks originate from the Decode PLD (DPLD) and are user-defined in PSDsoft.

Table 7 summarizes which versions of the PSD4000 contain which memory blocks.

Table 7. Memory Blocks

	Main	Flash	Seconda		
Device	Flash Size	Sector Size	Block Size	Sector Size	SRAM
PSD4135G2	512KB	64KB	32KB	8KB	8KB

9.1.1 Main Flash and Secondary Flash Memory Description

The main Flash memory block is divided evenly into eight sectors. The secondary Flash memory is divided into four sectors of eight Kbytes each. Each sector of either memory can be separately protected from program and erase operations.

Flash memory may be erased on a sector-by-sector basis and programmed word-by-word. Flash sector erasure may be suspended while data is read from other sectors of memory and then resumed after reading.

During a program or erase of Flash, the status can be output on the Rdy/Bsy pin of Port PE4. This pin is set up using PSDsoft.

9.1.1.1 Memory Block Selects

The decode PLD in the PSD4000 generates the chip selects for all the internal memory blocks (refer to the PLD section). Each of the eight Flash memory sectors have a Flash Select signal (FS0-FS7) which can contain up to three product terms. Each of the four Secondary Flash memory sectors have a Select signal (CSBOOT0-3) which can contain up to three product terms. Having three product terms for each sector select signal allows a given sector to be mapped in different areas of system memory. When using a microcontroller (80C51XA) with separate Program and Data space, these flexible select signals allow dynamic re-mapping of sectors from one space to the other before and after IAP.

9.1.1.2 The Ready/Busy Pin (PE4)

Pin PE4 can be used to output the Ready/Busy status of the PSD4000. The output on the pin will be a '0' (Busy) when Flash memory blocks are being written to, **or** when the Flash memory block is being erased. The output will be a '1' (Ready) when no write or erase operation is in progress.



9.1.1.3 Memory Operation

The main Flash and secondary Flash memories are addressed through the microcontroller interface on the PSD4000 device. The microcontroller can access these memories in one of two ways:

Beta Information

- □ The microcontroller can execute a typical bus write or read **operation** just as it would if accessing a RAM or ROM device using standard bus cycles.
- □ The microcontroller can execute a specific **instruction** that consists of several write and read operations. This involves writing specific data patterns to special addresses within the Flash to invoke an embedded algorithm. These instructions are summarized in Table 8.

Typically, Flash memory can be read by the microcontroller using read operations, just as it would read a ROM device. However, Flash memory can only be erased and programmed with specific instructions. For example, the microcontroller cannot write a single word directly to Flash memory as one would write a word to RAM. To program a word into Flash memory, the microcontroller must execute a program instruction sequence, then test the status of the programming event. This status test is achieved by a read operation or polling the Rdy/Busy pin (PE4).

The Flash memory can also be read by using special instructions to retrieve particular Flash device information (sector protect status and ID).

9.1.1.3.1 Instructions

An instruction is defined as a sequence of specific operations. Each received byte is sequentially decoded by the PSD and not executed as a standard write operation. The instruction is executed when the correct number of bytes are properly received and the time between two consecutive bytes is shorter than the time-out value. Some instructions are structured to include read operations after the initial write operations.

The sequencing of any instruction must be followed exactly. Any invalid combination of instruction bytes or time-out between two consecutive bytes while addressing Flash memory will reset the device logic into a read array mode (Flash memory reads like a ROM device).

The PSD4000 main Flash and secondary Flash support these instructions (see Table 8):

- Erase memory by chip or sector
- Suspend or resume sector erase
- Program a word
- Reset to read array mode
- Read Main Flash Identifier value
- Read sector protection status
- Bypass Instruction

These instructions are detailed in Table 8. For efficient decoding of the instructions, the first two bytes of an instruction are the coded cycles and are followed by a command byte or confirmation byte. The coded cycles consist of writing the data byte AAh to address XAAAh during the first cycle and data byte 55h to address X554h during the second cycle (unless the Bypass Instruction feature is used. See 9.1.1.7). Address lines A15-A12 are don't care during the instruction write cycles. However, the appropriate sector select signal (FSi or CSBOOTi) must be selected.

The main Flash and the secondary Flash Block have the same set of instructions (except Read main Flash ID). The chip selects of the Flash memory will determine which Flash will receive and execute the instruction. The main Flash is selected if any one of the FS0-7 is active, and the secondary Flash Block is selected if any one of the CSBOOT0-3 is active.



PSD4000 Series

The PSD4000 Functional Blocks (cont.)

Instruction (Note 14)	FS0-7 or CSB00T0-3	Cycle 1	Cycle 2	Cycle 3	Cycle 4	Cycle5	Cycle 6	Cycle 2
Read (Note 5)	1	"Read" RA RD						
Read Main Flash ID (Note 6)	1	AAh @XAAAh	55h @X554h	90h @XAAAh	"Read" ID @XX02h			
Read Sector Protection (Notes 6,8,13)	1	AAh @XAAAh	55h @X554h	90h @XAAAh	"Read" 00h or 01h @XX04h			
Program a Flash Word	1	AAh @XAAAh	55h @X554h	A0h @XAAAh	PD@PA			
Erase One Flash Sector	1	AAh @XAAAh	55h @X554h	80h @XAAAh	AAh @XAAAh	55h @X554h	30h @SA	30h @next \$ (Note 7
Erase Flash Block (Bulk Erase)	1	AAh @XAAAh	55h @X554h	80h @XAAAh	AAh @XAAAh	55h @X554h	10h @XAAAh	
Suspend Sector Erase (Note 11)	1	B0h @xxxh						
Resume Sector Erase (Note 12)	1	30h @xxxh						
Reset (Note 6)	1	F0 @ any address						
Unlock Bypass	1	AAh @XAAAh	55h @X554h	20h @XAAAh				
Unlock Bypass Program (Note 9)	1	A0h @XXXXh	PD@PA					
Unlock Bypass Reset (Note 10)	1	90h @XXXXh	00h @XXXXh					

X = Don't Care. "xxxh" address in the above table must be an even address.

RA = Address of the memory location to be read.

RD = Data read from location RA during read operation.

- PA = Address of the memory location to be programmed. Addresses are latched on the falling edge of the WR# (CNTL0) pulse. PA is an even address for PSD in word programming mode.
- PD = Data (word) to be programmed at location PA. Data is latched on the rising edge of WR# (CNTL0) pulse.
- SA = Address of the sector to be erased or verified. The chip select (FS0-7 or CSBOOT0-3) of the sector to be erased must be active (high).

NOTES:

- 1. All bus cycles are write bus cycle except the ones with the "read" label.
- 2. All values are in hexadecimal.
- 3. FS0-7 and CSBOOT0-3 are active high and are defined in PSDsoft.
- 4. Only Address bits A11-A0 are used in Instruction decoding.
- 5. No unlock or command cycles required when device is in read mode.
- 6. The Reset command is required to return to the read mode after reading the Flash ID, Sector Protect status or if DQ5 (DQ13) goes high.
- 7. Additional sectors to be erased must be entered within 80µs.
- 8. The data is 00h for an unprotected sector and 01h for a protected sector. In the fourth cycle, the sector chip select is active and (A1 = 1, A0 = 0).
- 9. The Unlock Bypass command is required prior to the Unlock Bypass Program command.
- 10. The Unlock Bypass Reset command is required to return to reading array data when the device is in the Unlock Bypass mode.
- 11. The system may read and program functions in non-erasing sectors, read the Flash ID or read the Sector Protect status, when in the Erase Suspend mode. The erase Suspend command is valid only during a sector erase operation.
- 12. The Erase Resume command is valid only during the Erase Suspend mode.
- 13. The MCU cannot invoke these instructions while executing code from the same Flash memory for which the instruction is intended. The MCU must fetch, for example, codes from the Secondary Flash memory when reading the Sector Protection Status of the main Flash.
- 14. All write bus cycles in an instruction are byte write to even address (XA4Ah or X554h). Flash Programming bys cycle is writing a word to even address.



9.1.1.4 Power-Up Condition

The PSD4000 internal logic is reset upon power-up to the read array mode. The FSi and CSBOOTi select signals, along with the write strobe signal, must be in the false state during power-up for maximum security of the data contents and to remove the possibility of data being written on the first edge of a write strobe signal. Any write cycle initiation is locked when V_{CC} is below VLKO.

9.1.1.5 Read

Under typical conditions, the microcontroller may read the Flash, or secondary Flash memories using read operations just as it would a ROM or RAM device. Alternately, the microcontoller may use read operations to obtain status information about a program or erase operation in progress. Lastly, the microcontroller may use instructions to read special data from these memories. The following sections describe these read functions.

9.1.1.5.1 Read the Contents of Memory

Main Flash and secodary Flash memories are placed in the read array mode after power-up, chip reset, or a Reset Flash instruction (see Table 8). The microcontroller can read the memory contents of main Flash or secondary Flash by using read operations any time the read operation is not part of an instruction sequence.

9.1.1.5.2 Read the Main Flash Memory Identifier

The main Flash memory identifier is read with an instruction composed of 4 operations: 3 specific write operations and a read operation (see Table 8). The PSD4000 main Flash memory ID is E8h. The Secondary Flash does not support this instruction.

9.1.1.5.3 Read the Flash Memory Sector Protection Status

The Flash memory sector protection status is read with an instruction composed of 4 operations: 3 specific write operations and a read operation (see Table 8). The read operation will produce 01h if the Flash sector is protected, or 00h if the sector is not protected.

The sector protection status for all NVM blocks (main Flash or secondary Flash) can also be read by the microcontroller accessing the Flash Protection and Flash Boot Protection registers in PSD I/O space. See section 9.1.1.9.1 for register definitions.

9.1.1.5.4 Read the Erase/Program Status Bits

The PSD4000 provides several status bits to be used by the microcontroller to confirm the completion of an erase or programming instruction of Flash memory. These status bits minimize the time that the microcontroller spends performing these tasks and are defined in Table 9. The status byte resides in even location and can be read as many times as needed. Please note DQ15-8 is even byte for Motorola MCUs with 16 bit data bus.

Table 9. Status Bits

	FSi/ CSB00Ti	DQ7	DQ6	DQ5	DQ4	DQ3	DQ2	DQ1	DQO
Flash	V _{IH}	Data Polling	Toggle Flag	Error Flag	х	Erase Time- out	х	х	х

Table 9A. Status Bits for Motorola

	FSi/ CSB00Ti	DQ15	DQ14	DQ13	DQ12	DQ11	DQ10	DQ9	DQ8
Flash	V _{IH}	Data Polling	Toggle Flag	Error Flag	х	Erase Time- out	х	х	х

NOTES: 1. X = Not guaranteed value, can be read either 1 or 0.

2. DQ15-DQ0 represent the Data Bus bits, D15-D0.

3. FSi/CSBOOTi are active high.

For Flash memory, the microcontroller can perform a read operation to obtain these status bits while an erase or program instruction is being executed by the embedded algorithm. See section 9.1.1.6 for details.



9.1.1.5.5 Data Polling Flag DQ7 (DQ15 for Motorola)

When Erasing or Programming the Flash memory bit DQ7 (DQ15) outputs the complement of the bit being entered for Programming/Writing on DQ7 (DQ15). Once the Program instruction or the Write operation is completed, the true logic value is read on DQ7 (DQ15) (in a Read operation). Flash memory specific features:

- □ Data Polling is effective after the fourth Write pulse (for programming) or after the sixth Write pulse (for Erase). It must be performed at the address being programmed or at an address within the Flash sector being erased.
- □ During an Erase instruction, DQ7 (DQ15) outputs a '0'. After completion of the instruction, DQ7 (DQ15) will output the last bit programmed (it is a '1' after erasing).
- □ If the location to be programmed is in a protected Flash sector, the instruction is ignored.
- □ If all the Flash sectors to be erased are protected, DQ7 (DQ15) will be set to '0' for about 100 µs, and then return to the previous addressed location. No erasure will be performed.

9.1.1.5.6 Toggle Flag DQ6 (DQ14 for Motorola)

The PSD4000 offers another way for determining when the Flash memory Program instruction is completed. During the internal Write operation and when either the FSi or CSBOOTi is true, the DQ6 (DQ14) will toggle from '0' to '1' and '1' to '0' on subsequent attempts to read any word of the memory.

When the internal cycle is complete, the toggling will stop and the data read on the Data Bus is the addressed memory location. The device is now accessible for a new Read or Write operation. The operation is finished when two successive reads yield the same output data. Flash memory specific features:

- □ The Toggle bit is effective after the fourth Write pulse (for programming) or after the sixth Write pulse (for Erase).
- □ If the location to be programmed belongs to a protected Flash sector, the instruction is ignored.
- □ If all the Flash sectors selected for erasure are protected, DQ6 (DQ14) will toggle to '0' for about 100 µs and then return to the previous addressed location.

9.1.1.5.7 Error Flag DQ5 (DQ14 for Motorola)

During a correct Program or Erase, the Error bit will set to '0'. This bit is set to '1' when there is a failure during Flash programming, Sector erase, or Bulk Erase.

In the case of Flash programming, the Error Bit indicates the attempt to program a Flash bit(s) from the programmed state (0) to the erased state (1), which is not a valid operation. The Error bit may also indicate a timeout condition while attempting to program a word.

In case of an error in Flash sector erase or word program, the Flash sector in which the error occurred or to which the programmed location belongs must no longer be used. Other Flash sectors may still be used. The Error bit resets after the Reset instruction. A reset instruction is required after detecting the error bit.

9.1.1.5.8 Erase Time-out Flag DQ3 (DQ11 for Motorola)

The Erase Timer bit reflects the time-out period allowed between two consecutive Sector Erase instructions. The Erase timer bit is set to '0' after a Sector Erase instruction for a time period of 100 μ s + 20% unless an additional Sector Erase instruction is decoded. After this time period or when the additional Sector Erase instruction is decoded, DQ3 (DQ11) is set to '1'. A reset instruction is required after detecting the erase timer bit.



9.1.1.6 Programming Flash Memory

Flash memory must be erased prior to being programmed. The MCU may erase Flash memory all at once or by-sector. Flash memory sector erases to all logic ones, and its bits are programmed to logic zeros. Although erasing Flash memory occurs on a sector or chip basis, programming Flash memory occurs on a word basis.

Beta Information

The PSD4000 main Flash and secondary Flash memories require the MCU to send an instruction to program a word or perform an erase function (see Table 8).

Once the MCU issues a Flash memory program or erase instruction, it must check for the status of completion. The embedded algorithms that are invoked inside the PSD4000 support several means to provide status to the MCU. Status may be checked using any of three methods: Data Polling, Data Toggle, or the Ready/Busy output pin.

9.1.1.6.1 Data Polling

Polling on DQ7 (DQ15) is a method of checking whether a Program or Erase instruction is in progress or has completed. Figure 3 shows the Data Polling algorithm.

When the MCU issues a programming instruction, the embedded algorithm within the PSD4000 begins. The MCU then reads the location of the word to be programmed in Flash to check status. Data bit DQ7 (DQ15) of this location becomes the compliment of data bit 7of the original data word to be programmed. The MCU continues to poll this location, comparing DQ7 (DQ15) and monitoring the Error bit on DQ5 (DQ13). When the DQ7 (DQ15) matches data bit 7 of the original data, and the Error bit at DQ5 (DQ13) remains '0', then the embedded algorithm is complete. If the Error bit at DQ5 is '1', the MCU should test DQ7 (DQ15) again since DQ7 (DQ15) may have changed simultaneously with DQ5 (DQ13) (see Figure 3).

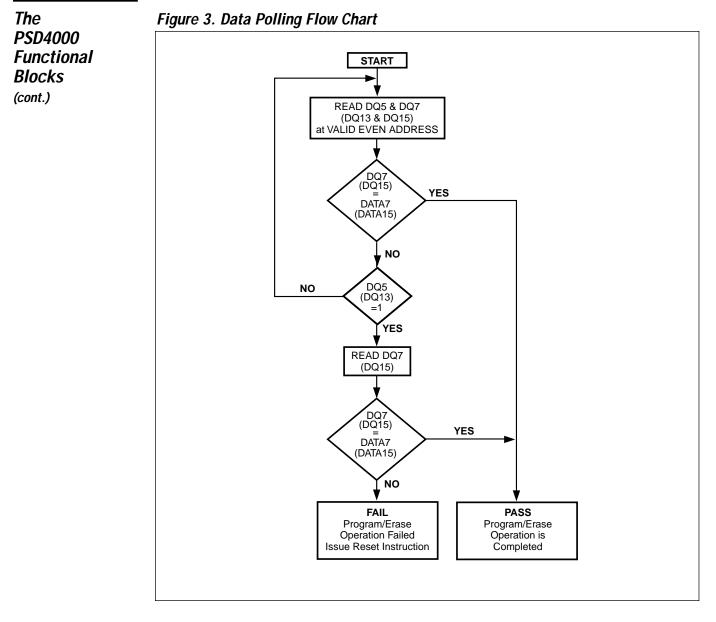
The Error bit at DQ5 (DQ13) will be set if either an internal timeout occurred while the embedded algorithm attempted to program the location or if the MCU attempted to program a '1' to a bit that was not erased (not erased is logic '0').

It is suggested (as with all Flash memories) to read the location again after the embedded programming algorithm has completed to compare the word that was written to Flash with the word that was intended to be written.

When using the Data Polling method after an erase instruction, Figure 3 still applies. However, DQ7 (DQ15) will be '0' until the erase operation is complete. A '1' on DQ5 (DQ13) will indicate a timeout failure of the erase operation, a '0' indicates no error. The MCU can read any location within the sector being erased to get DQ7 (DQ15) and DQ5 (DQ13).

PSDsoft generates ANSI C code functions which implement these Data Polling algorithms.





9.1.1.6.2 Data Toggle

Checking the Data Toggle bit on DQ6 (DQ14) is a method of determining whether a Program or Erase instruction is in progress or has completed. Figure 4 shows the Data Toggle algorithm.

When the MCU issues a programming instruction, the embedded algorithm within the PSD4000 begins. The MCU then reads the location to be programmed in Flash to check status. Data bit DQ6 (DQ14) of this location will toggle each time the MCU reads this location until the embedded algorithm is complete. The MCU continues to read this location, checking DQ6 (DQ14) and monitoring the Error bit on DQ5 (DQ13). When DQ6 (DQ14) stops toggling (two consecutive reads yield the same value), and the Error bit on DQ5 (DQ13) remains '0', then the embedded algorithm is complete. If the Error bit on DQ5 (DQ13) is '1', the MCU should test DQ6 (DQ14) again, since DQ6 (DQ14) may have changed simultaneously with DQ5 (DQ13) (see Figure 4).

The Error bit at DQ5 (DQ13) will be set if either an internal timeout occurred while the embedded algorithm attempted to program, or if the MCU attempted to program a '1' to a bit that was not erased (not erased is logic '0').



9.1.1.6.2 Data Toggle (cont.)

It is suggested (as with all Flash memories) to read the location again after the embedded programming algorithm has completed to compare the word that was written to Flash with the word that was intended to be written.

Beta Information

When using the Data Toggle method after an erase instructin, Figure 4 still applies. DQ6 (DQ14) will toggle until the erase operation is complete. A '1' on DQ5 (DQ13) will indicate a timeout failure of the erase operation, a '0' indicates no error. The MCU can read any even location within the sector being erased to get DQ6 (DQ14) and DQ5 (DQ13).

PSDsoft generates ANSI C code functions which implement these Data Toggling algorithms.

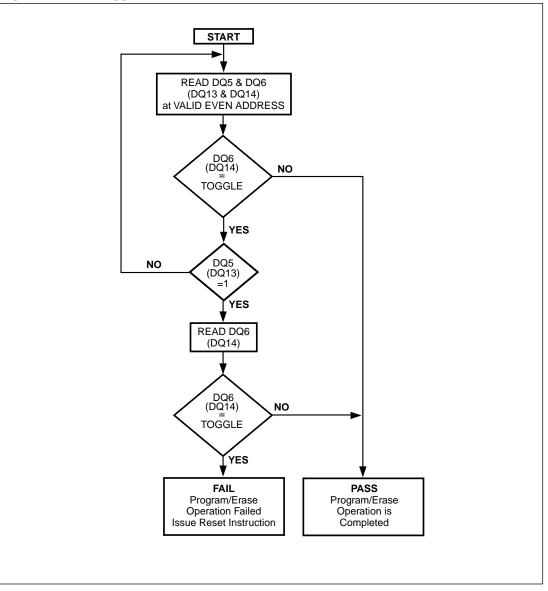


Figure 4. Data Toggle Flow Chart

9.1.1.7 Unlock Bypass Instruction

The unlock bypass feature allows the system to program words to the flash memories faster than using the standard program instruction. The unlock bypass instruction is initiated by first writing two unlock cycles. This is followed by a third write cycle containing the unlock bypass command, 20h (see Table 8). The flash memory then enters the unlock bypass mode. A two-cycle Unlock Bypass Program instruction is all that is required to program in this mode. The first cycle in this instruction contains the unlock bypass programm command, A0h; the second cycle contains the program address and data. Additional data is programmed in the same manner. This mode dispenses with the initial two unlock cycles required in the standard program instruction, resulting in faster total programming time. During the unlock bypass mode, only the Unlock Bypass Program and Unlock Bypass Reset instructions are valid. To exit the unlock bypass mode, the system must issue the two-cycle unlock bypass reset instruction. The first cycle must contain the data 90h; the second cycle the data 00h. Addresses are don't care for both cycles. The flash memory then returns to reading array data mode.

9.1.1.8 Erasing Flash Memory

9.1.1.8.1. Flash Bulk Erase Instruction

The Flash Bulk Erase instruction uses six write operations followed by a Read operation of the status register, as described in Table 8. If any byte of the Bulk Erase instruction is wrong, the Bulk Erase instruction aborts and the device is reset to the Read Flash memory status.

During a Bulk Erase, the memory status may be checked by reading status bits DQ5, DQ6, and DQ7 (DQ13, DQ14, DQ15), as detailed in section 9.1.1.6. The Error bit (returns a '1' if there has been an Erase Failure (maximum number of erase cycles have been executed).

It is not necessary to program the array with 00h because the PSD4000 will automatically do this before erasing to 0FFh.

During execution of the Bulk Erase instruction, the Flash memory will not accept any instructions.

9.1.1.8.2 Flash Sector Erase Instruction

The Sector Erase instruction uses six write operations, as described in Table 8. Additional Flash Sector Erase confirm commands and Flash sector addresses can be written subsequently to erase other Flash sectors in parallel, without further coded cycles, if the additional instruction is transmitted in a shorter time than the timeout period of about 100 μ s. The input of a new Sector Erase instruction will restart the time-out period.

The status of the internal timer can be monitored through the level of DQ3 (DQ11) (Erase time-out bit). If DQ3 (DQ11) is '0', the Sector Erase instruction has been received and the timeout is counting. If DQ3 (DQ11) is '1', the timeout has expired and the PSD4000 is busy erasing the Flash sector(s). Before and during Erase timeout, any instruction other than Erase suspend and Erase Resume will abort the instruction and reset the device to Read Array mode. It is not necessary to program the Flash sector with 00h as the PSD4000 will do this automatically before erasing.

During a Sector Erase, the memory status may be checked by reading status bits DQ5, DQ6, and DQ7 (DQ13, DQ14, DQ15), as detailed in section 9.1.1.6.

During execution of the erase instruction, the Flash block logic accepts only Reset and Erase Suspend instructions. Erasure of one Flash sector may be suspended, in order to read data from another Flash sector, and then resumed.



9.1.1.8.3 Flash Erase Suspend Instruction

Beta Information

When a Flash Sector Erase operation is in progress, the Erase Suspend instruction will suspend the operation by writing 0B0h to any even address when an appropriate Chip Select (FSi or CSBOOTi) is true. (See Table 8). This allows reading of data from another Flash sector after the Erase operation has been suspended. Erase suspend is accepted only during the Flash Sector Erase instruction execution and defaults to read array mode. An Erase Suspend instruction executed during an Erase timeout will, in addition to suspending the erase, terminate the time out.

The Toggle Bit DQ6 stops toggling when the PSD4000 internal logic is suspended. The toggle Bit status must be monitored at an address within the Flash sector being erased. The Toggle Bit will stop toggling between 0.1 μ s and 15 μ s after the Erase Suspend instruction has been executed. The PSD4000 will then automatically be set to Read Flash Block Memory Array mode.

If an Erase Suspend instruction was executed, the following rules apply:

- Attempting to read from a Flash sector that was being erased will output invalid data.
- Reading from a Flash sector that was **not** being erased is valid.
- The Flash memory **cannot** be programmed, and will only respond to Erase Resume and Reset instructions (read is an operation and is OK).
- If a Reset instruction is received, data in the Flash sector that was being erased will be invalid.

9.1.1.8.4 Flash Erase Resume Instruction

If an Erase Suspend instruction was previously executed, the erase operation may be resumed by this instruction. The Erase Resume instruction consists of writing 030h to any even address while an appropriate Chip Select (FSi or CSBOOTi) is true. (See Table 8.)

9.1.1.9 Specific Features

9.1.1.9.1 Main Flash and Secondary Flash Sector Protect

Each sector of Main Flash and Secondary Flash memory can be separately protected against Program and Erase functions. Sector Protection provides additional data security because it disables all program or erase operations. This mode can be activated (or deactivated) through the JTAG-ISP Port or a Device Programmer.

Sector protection can be selected for each sector using the PSDsoft program. This will automatically protect selected sectors when the device is programmed through the JTAG Port or a Device Programmer. Flash sectors can be unprotected to allow updating of their contents using the JTAG Port or a Device Programmer. The microcontroller can read (but cannot change) the sector protection bits.

Any attempt to program or erase a protected Flash sector will be ignored by the device. The Verify operation will result in a read of the protected data. This allows a guarantee of the retention of the Protection status.

The sector protection status can either be read by the MCU through the Flash protection and secondary Flash protection registers (CSIOP), or use the Read Sector Protection instruction (Table 8).



Bit 0

Sec0_Prot

Bit 1

The Table 10. Sector Protection/Security Bit Definition **PSD4000** Flash Protection Register Functional Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 **Blocks** Sec7_Prot Sec6_Prot Sec5_Prot Sec4_Prot Sec1_Prot Sec3_Prot Sec2_Prot (cont.) Bit Definitions:

1 = Main Flash Sector <i> is write protected. Sec<i> Prot

Sec<i>_Prot 0 = Main Flash Sector <i> is not write protected.

Flash Boot Protection Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Security_ Bit	*	*	*	Sec3_Prot	Sec2_Prot	Sec1_Prot	Sec0_Prot

*: Not used.

Bit Definitions:

Sec <i>_Prot Sec<i>_Prot</i></i>	 1 = Flash Boot Sector <i> is write protected.</i> 0 = Flash Boot Sector <i> is not write protected.</i>
Security_Bit	0 = Security Bit in device has not been set.1 = Security Bit in device has been set.

9.1.1.9.2 Reset Instruction

The Reset instruction consists of one write cycle (see Table 8). It can also be optionally preceded by the standard two write decoding cycles (writing AAh to AAAh and 55h to 554h).

The Reset instruction must be executed after:

- 1. Reading the Flash Protection status or Flash ID using the Flash instruction.
- 2. When an error condition occurs (DQ5 (DQ13) goes high) during a Flash programming or erase cycle.

The Reset instruction will reset the Flash to normal Read Mode immediately. However, if there is an error condition (DQ5 (DQ13) goes high), the Flash memory will return to the Read Mode in 25 µSeconds after the Reset instruction is issued.

The Reset instruction is ignored when it is issued during a Flash programming or Bulk Erase cycle. The Reset instruction will abort the on going sector erase cycle and return the Flash memory to normal Read Mode in 25 µSeconds.

9.1.1.9.3 Reset Pin Input

The reset pulse input from the pin will abort any operation in progress and reset the Flash memory to Read Mode. When the reset occurs during a programming or erase cycle, the Flash memory will take up to 25 µSeconds to return to Read Mode. It is recommended that the reset pulse (except power on reset, see Reset Section) be at least 25 µSeconds such that the Flash memory will always be ready for the MCU to fetch the boot code after reset is over.



9.1.2 SRAM

The SRAM is enabled when RS0—the SRAM chip select output from the DPLD—is high. RS0 can contain up to three product terms, allowing flexible memory mapping.

The SRAM can be backed up using an external battery. The external battery should be connected to the Vstby pin (PE6). If you have an external battery connected to the PSD4000, the contents of the SRAM will be retained in the event of a power loss. The contents of the SRAM will be retained so long as the battery voltage remains at 2V or greater. If the supply voltage falls below the battery voltage, an internal power switchover to the battery occurs.

Pin PE7 can be configured as an output that indicates when power is being drawn from the external battery. This Vbaton signal will be high with the supply voltage falls below the battery voltage and the battery on PE6 is supplying power to the internal SRAM.

The chip select signal (RS0) for the SRAM, Vstby, and Vbaton are all configured using PSDsoft.

9.1.3 Memory Select Signals

The main Flash (FSi), secondary Flash (CSBOOTi), and SRAM (RS0) memory select signals are all outputs of the DPLD. They are defined using PSDsoft. The following rules apply to the equations for the internal chip select signals:

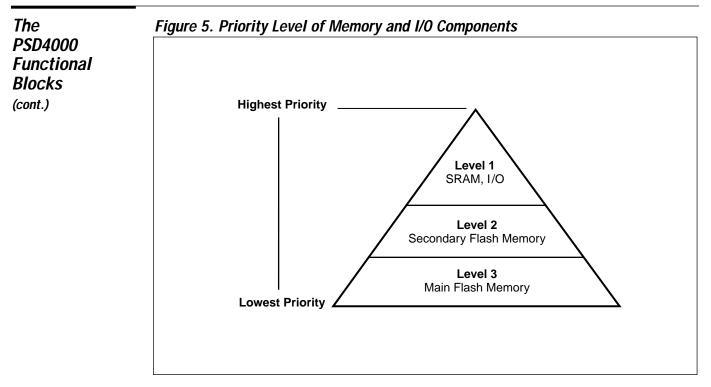
- 1. Main Flash memory and secondary Flash memory sector select signals must **not** be larger than the physical sector size.
- 2. Any main Flash memory sector must **not** be mapped in the same memory space as another Main Flash sector.
- 3. A secondary Flash memory sector must **not** be mapped in the same memory space as another Flash Boot sector.
- 4. SRAMand I/O spaces must not overlap.
- 5. A secondary Flash memory sector **may** overlap a main Flash memory sector. In case of overlap, priority will be given to the Flash Boot sector.
- 6. SRAM, I/O, and Peripheral I/O spaces **may** overlap any other memory sector. Priority will be given to the SRAM, and I/O.

Example

FS0 is valid when the address is in the range of 8000h to BFFFh, CSBOOT0 is valid from 8000h to 9FFFh, and RS0 is valid from 8000h to 87FFh. Any address in the range of RS0 will always access the SRAM. Any address in the range of CSBOOT0 greater than 87FFh (and less than 9FFFh) will automatically address Boot memory segment 0. Any address greater than 9FFFh will access the Flash memory segment 0. You can see that half of the Flash memory segment 0 and one-fourth of Boot segment 0 can not be accessed in this example. Also note that an equation that defined FS1 to anywhere in the range of 8000h to BFFFh would **not** be valid.

Figure 5 shows the priority levels for all memory components. Any component on a higher level can overlap and has priority over any component on a lower level. Components on the same level must **not** overlap. Level one has the highest priority and level 3 has the lowest.





9.1.3.1. Memory Select Configuration for MCUs with Separate Program and Data Spaces

The 80C51XA and compatible family of microcontrollers, can be configured to have separate address spaces for code memory (selected using PSEN) and data memory (selected using RD). Any of the memories within the PSD4000 can reside in either space or both spaces. This is controlled through manipulation of the VM register that resides in the PSD's CSIOP space.

The VM register is set using PSDsoft to have an initial value. It can subsequently be changed by the microcontroller so that memory mapping can be changed on-the-fly. For example, you may wish to have SRAM and main Flash in Data Space at boot, and secondary Flash memory in Program Space at boot, and later swap main and secondary Flash memory. This is easily done with the VM register by using PSDsoft to configure it for boot up and having the microcontroller change it when desired.

Table 11 describes the VM Register.

Bit 7 PIO_EN	Bit 6*	<i>Bit 5*</i>	Bit 4 FL_Data	Bit 3 Boot_Data	Bit 2 FL_Code	Bit 1 Boot_Code	Bit 0 SRAM_Code
0 = disable PIO mode	*	*	0 = RD can't access Flash	0 = RD can't access Boot Flash	0 = PSEN can't access Flash	0 = PSEN can't access Boot Flash	0 = PSEN can't access SRAM
1= enable PIO mode	*	*	1 = RD access Flash	1 = RD access Boot Flash	1 = PSEN access Flash	1 = PSEN access Boot Flash	1 = PSEN access SRAM

Table 11. VM Register

NOTE: Bits 6-5 are not used.



9.1.3.2 Configuration Modes for MCUs with Separate Program and Data Spaces

9.1.3.2.1 Separate Space Modes

Code memory space is separated from data memory space. For example, the PSEN signal is used to access the program code from the main Flash Memory, while the RD signal is used to access data from the secondary Flash memory, SRAM and I/O Ports. This configuration requires the VM register to be set to 0Ch.

9.1.3.2.2 . Combined Space Modes

The program and data memory spaces are combined into one space that allows the main Flash Memory, secondary Flash memory, and SRAM to be accessed by either PSEN or RD. For example, to configure the main Flash memory in combined space mode, bits 2 and 4 of the VM register are set to "1".

9.1.3.3 80C51XA Memory Map Example

See Application Notes for examples.



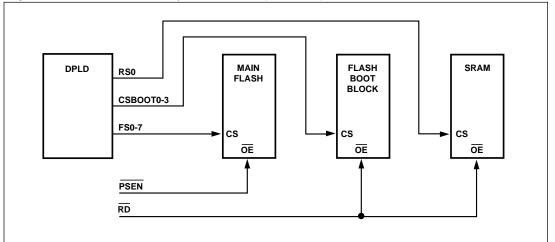
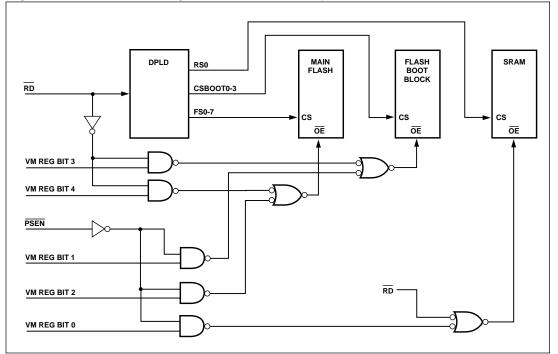


Figure 7. 80C51XA Memory Mode – Combined Space Mode





9.1.4 Page Register

The eight bit Page Register increases the addressing capability of the microcontroller by a factor of up to 256. The contents of the register can also be read by the microcontroller. The outputs of the Page Register (PGR0-PGR7) are inputs to the PLD decoder and can be included in the Flash Memory, secondary Flash memory, and SRAM chip select equations.

If memory paging is not needed, or if not all 8 page register bits are needed for memory paging, then these bits may be used in the PLD for general logic. See Application Notes.

Figure 8 shows the Page Register. The eight flip flops in the register are connected to the internal data bus. The microcontroller can write to or read from the Page Register. The Page Register can be accessed at address location CSIOP + E0h.

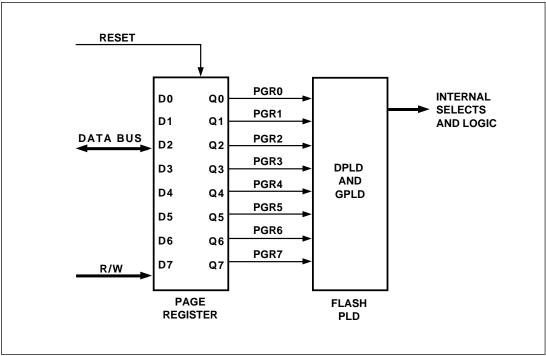


Figure 8. Page Register



9.1.5 Memory ID Registers

The 8-bit read only memory status registers are included in the CSIOP space. The user can determine the memory configuration of the PSD device by reading the Memory ID0 and Memory ID1 registers. The content of the registers are defined as follow:

Memory_ID0 Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
S_size 3	S_size 2	S_size 1	S_size 0	F_size 3	F_size 2	F_size 1	F_size 0

Bit Definition

F_size3	F_size2	F_size1	F_size0	Main Flash Size (Bit)
0	0	0	0	none
0	0	0	1	256K
0	0	1	0	512K
0	0	1	1	1M
0	1	0	0	2M
0	1	0	1	4M
0	1	1	0	8M

S_size3	S_size2	S_size1	S_size0	SRAM Size (Bit)
0	0	0	0	none
0	0	0	1	16K
0	0	1	0	32K
0	0	1	1	64K

Memory_ID1 Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
*	*	B_type 1	B_type 0	B_size 3	B_size 2	B_size 1	B_size 0

*Not used bit should be set to zero.

Bit Definition

B_size3	B_size2	B_size1	B_size0	Boot Block Size (Bit)
0	0	0	0	none
0	0	0	1	128K
0	0	1	0	256K
0	0	1	1	512K

B_type1	B_type0	Boot Block Type
0	0	Flash
0	1	EEPROM



9.2 PLDs

The PLDs bring programmable logic functionality to the PSD4000. After specifying the logic for the PLDs in PSDsoft, the logic is programmed into the device and available upon power-up.

The PSD4000 contains two PLDs: the Decode PLD (DPLD), and the General Purpose PLD (GPLD). The PLDs are briefly discussed in the next few paragraphs, and in more detail in sections 9.2.1 and 9.2.2. Figure 10 shows the configuration of the PLDs.

The DPLD performs address decoding for internal components, such as memory, registers, and I/O port selects.

The GPLD can be used to generate external chip selects, control signals or logic functions. The GPLD has 24 outputs that are connected to Port A, B and C.

The AND array is used to form product terms. These product terms are specified using PSDsoft. An Input Bus consisting of 66 signals is connected to the PLDs. The signals are shown in Table 12. The complement of the 66 signals are also available as inputs to the AND array.

Input Source	Input Name	Number of Signals
MCU Address Bus	A[15:0]*	16
MCU Control Signals	CNTL[2:0]	3
Reset	RST	1
Power Down	PDN	1
Port A Input	PA[7-0]	8
Port B Input	PB[7-0]	8
Port C Input	PC[7-0]	8
Port D Inputs	PD[3:0]	4
Port F Inputs	PF[7:0]	8
Page Register	PGR(7:0)	8
Flash Programming Status Bit	Rdy/Bsy	1

Table 12. DPLD and GPLD Inputs

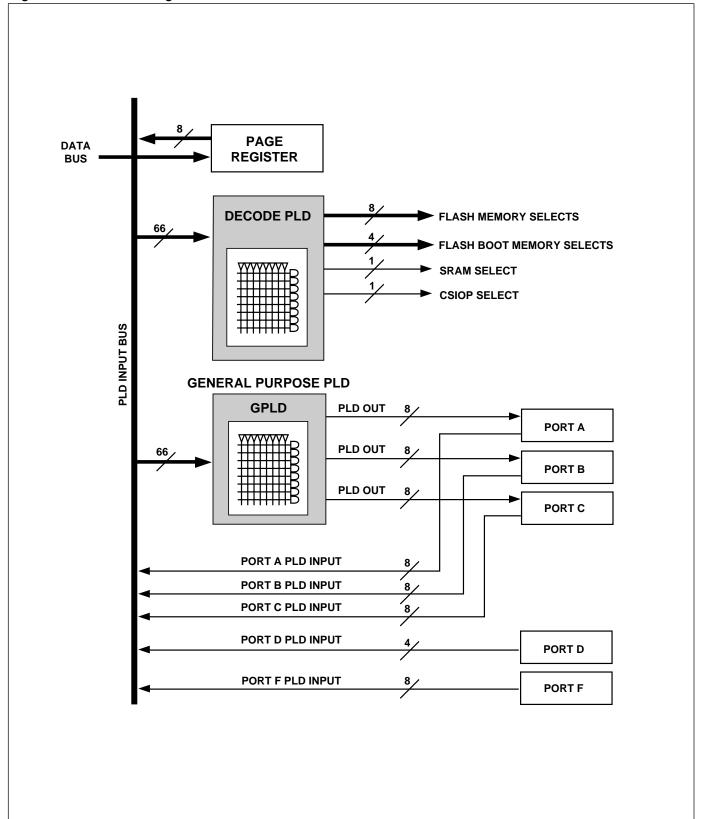
NOTE: The address inputs are A[19:4] in 80C51XA mode.

The Turbo Bit

The PLDs in the PSD4000 can minimize power consumption by switching to standby when inputs remain unchanged for an extended time of about 70 ns. Setting the Turbo mode bit to off (Bit 3 of the PMMR0 register) automatically places the PLDs into standby if no inputs are changing. Turbo-off mode increases propagation delays while reducing power consumption. Refer to the Power Management Unit section on how to set the Turbo Bit. Additionally, five bits are available in the PMMR2 register to block MCU control signals from entering the PLDs. This reduces power consumption and can be used only when these MCU control signals are not used in PLD logic equations.



Figure 9. PLD Block Diagram





9.2.1 Decode PLD (DPLD)

The DPLD, shown in Figure 10, is used for decoding the address for internal components. The DPLD can generate the following decode signals:

- 8 sector selects for the main Flash memory (three product terms each)
- 4 sector selects for the Secondary Flash memory (three product terms each)
- 1 internal SRAM select (three product terms)
- 1 internal CSIOP select (select PSD registers, one product term)

Inputs to the DPLD chip selects may include address inputs, Page Register inputs and other user defined external inputs from Ports A, B, C, D or F.

9.2.2 General Purpose PLD (GPLD)

The General Purpose PLD implements user defined system combinatorial logic function or chip selects for external devices. Figure 11 shows how the GPLD is connected to the I/O Ports. The GPLD has 24 outputs and each are routed to a port pin. The port pin can also be configured as input to the GPLD. When it is not used as GPLD output or input, the pin can be configured to perform other I/O functions.

All GPLD outputs are identical except in the number of available product terms (PTs) for logic implementation. Select the pin that can best meet the PT requirement of your logic function or chip select. In general, a PT is consumed for each logic "OR" function that you specify in PSDsoft. However, certain logic functions can consume more than one PT even if no logic "OR" is specified (such as specifying an address range with boundaries of high granularity).

Table 13 shows the number of "native" PTs for each GPLD output pin. A native PT means that a particular PT is dedicated to an output pin. For example, Table 13 shows that PSD Port A pin PA0 has 3 native product terms. This means a guaranteed minimum of 3 PTs is available to implement logic for that pin.

PSD silicon and PSDsoft can include additional PTs beyong the native PTs to implement logic. This is a transparent operation that occurs as needed through PT expansion (internal feedback) or PT allocation (internal borrowing). You may notice in the fitter report generated by PSDsoft that for a given GPLD output pin, more PTs were used to implement logic than the number of native PTs available for that pin. This is because PSDsoft has called on unused PTs from other GPLD output pins to make your logic design fit (PT allocation or PT expansion). For optimum results, choose a GPLD output pin with a large number of native PTs for complicated logic.

GPLD Output on Port Pin	Number of Native Product Terms
Port A, pins PA0-3	3
Port A, pins PA4-7	9
Port B, pins PB0-3	4
Port B, pins PB4-7	7
Port C, pins PC0-7	1

Table 13. GPLD Product Term Availability



Figure 10. DPLD Logic Array

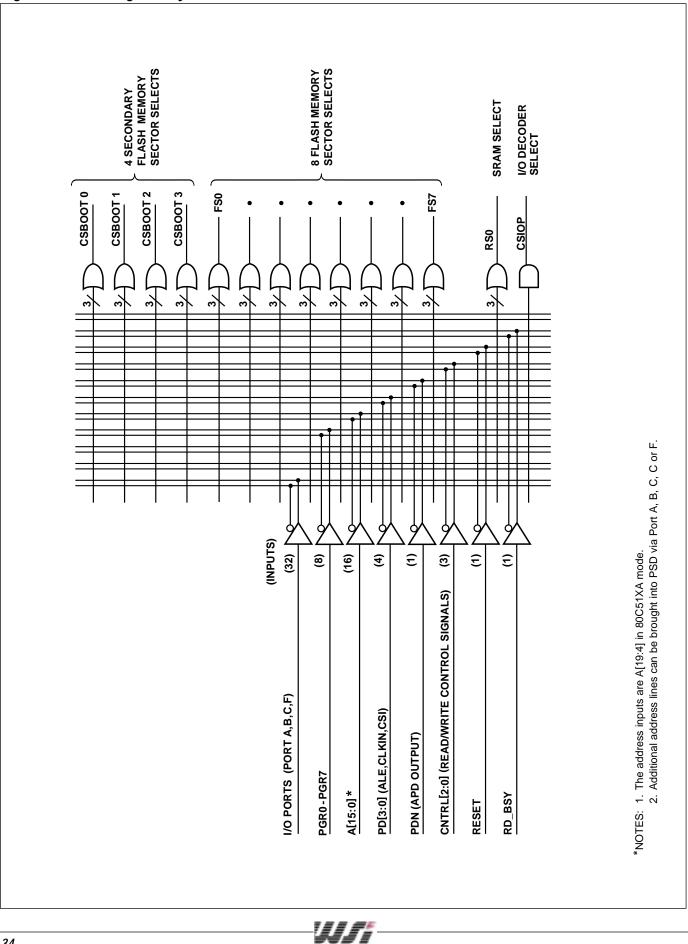
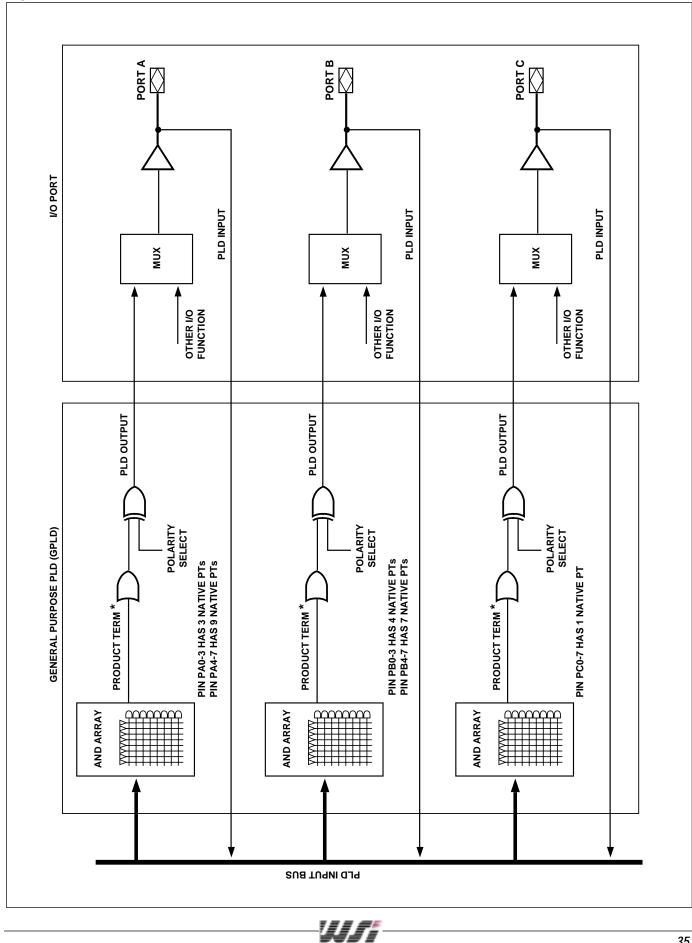


Figure 11. The Micro⇔Cell and I/O Port



9.3 Microcontroller Bus Interface

The "no-glue logic" PSD4000 Microcontroller Bus Interface can be directly connected to most popular microcontrollers and their control signals. Key 16-bit microcontrollers with their bus types and control signals are shown in Table 14. The MCU interface type is specified using the PSDsoft.

МСИ	CNTLO	CNTL1	CNTL2	PD3	PD0**	ADIO0	PF3-PF0
68302, 68306 MMC2001	R/W	LDS	UDS	*	AS	—	*
68330, 68331 68332, 68340	R/W	DS	SIZ0	*	AS	A0	*
68LC302, MMC2001	WEL	ŌĒ		WEH	AS	-	*
68HC16	R/W	DS	SIZ0	*	AS	A0	*
68HC912	R/W	Е	LSTRB	DBE	E	A0	*
68HC812***	R/W	E	LSTRB	*	*	A0	*
80196	WR	RD	BHE	*	ALE	A0	*
80196SP	WRL	RD	*	WRH	ALE	A0	*
80186	WR	RD	BHE	*	ALE	A0	*
80C161 80C164-80C167	WR	RD	BHE	*	ALE	A0	*
80C51XA	WRL	RD	PSEN	WRH	ALE	A4/D0	A3-A1
H8/3044	WRL	RD	*	WRH	AS	A0	_
M37702M2	R/W	Ē	BHE	*	ALE	A0	*

Table 14. Microcontrollers and their Control Signals

*Unused CNTL2 pin can be configured as GPLD input. Other unused pins (PD3-0, PF3-0) can be configured for other I/O functions.

**ALE/AS input is optional for microcontrollers with a non-multiplexed bus.

***This configuration is for 68C812A4_EC at 5MHz, 3V only.

9.3.1. PSD4000 Interface to a Multiplexed Bus

Figure 16 shows an example of a system using a microcontroller with a 16-bit multiplexed bus and a PSD4000. The ADIO port on the PSD4000 is connected directly to the microcontroller address/data bus. ALE latches the address lines internally. Latched addresses can be brought out to Port E, F or G. The PSD4000 drives the ADIO data bus only when one of its internal resources is accessed and the RD input is active. Should the system address bus exceed sixteen bits, Ports A, B, C, or F may be used as additional address inputs.

9.3.2. PSD4000 Interface to a Non-Multiplexed Bus

Figure 17 shows an example of a system using a microcontroller with a 16-bit non-multiplexed bus and a PSD4000. The address bus is connected to the ADIO Port, and the data bus is connected to Port F and G. Port F and G are in tri-state mode when the PSD4000 is not accessed by the microcontroller. Should the system address bus exceed sixteen bits, Ports A, B or C may be used for additional address inputs.



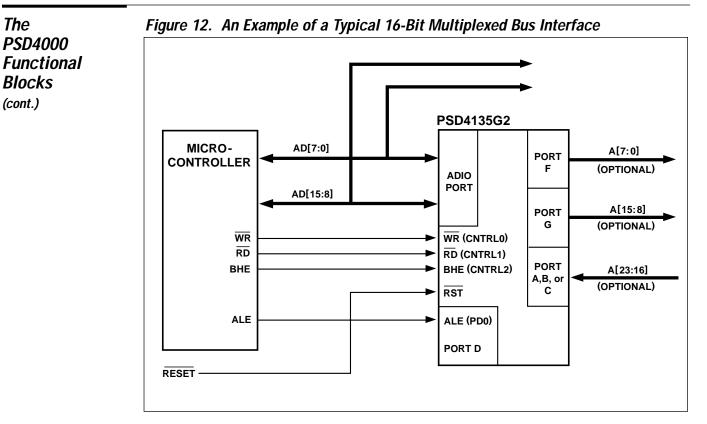
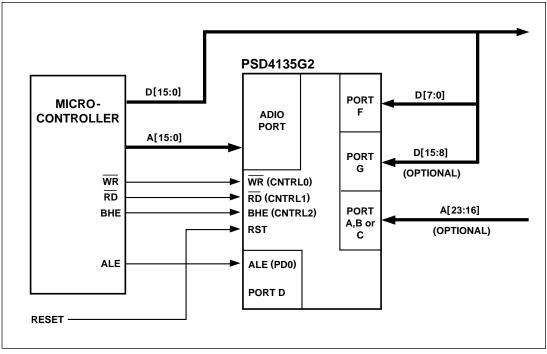


Figure 13. An Example of a Typical 16-Bit Non-Multiplexed Bus Interface



us:

9.3.3 Data Byte Enable Reference

Microcontrollers have different data byte orientations. The following tables show how the

Beta Information

PSD4135G2 interprets byte/word operation in different bus write configurations. Even-byte refers to locations with address A0 equal to zero and odd byte as locations with A0 equal to one.

9.3.4 Microcontroller Interface Examples

Figures 14 through 17 show examples of the basic connections between the PSD4135G2 and some popular microcontrollers. The PSD4135G2 Control input pins are labeled as the microcontroller function for which they are configured. The MCU interface is specified using PSDsoft. The PE6 pin should be grounded if Vstby is not used.

9.3.4.1 80C196 and 80C186

In Figure 14, the Intel 80C196 microcontroller, which has a multiplexed sixteen-bit bus, is shown connected to a PSD4135G2. The WR and RD signals are connected to the CNTL0-1 pins. The BHE signal is used for high data byte selection. If BHE is not used, the PSD can be configured to receive the WRL and WRH from the MCU. Higher address inputs (A16-A19) can be routed to Port A, B or C as inputs to the PLD.

The AMD 80186 family has the same bus connection to the PSD as the 80C196.

BHE	A0	D15-D8	D7-D0
0	0	Odd Byte	Even Byte
0	1	Odd Byte	-
1	0	-	Even Byte

Table 15. 16-Bit Data Bus with BHE

Table 16. 16-Bit Data Bus with WRH and WRL

WRH	WRL	D15-D8	D7-D0
0	0	Odd Byte	Even Byte
0	1	Odd Byte	_
1	0	_	Even Byte

Table 17. 16-Bit Data Bus with SIZO, AO (Motorola MCU)

SIZ0	A0	D15-D8	D7-D0
0	0	Even Byte	Odd Byte
1	0	Even Byte	-
1	1	_	Odd Byte

Table 18. 16-Bit Data Bus with UDS, LDS (Motorola MCU)

LDS	UDS	D15-D8	D7-D0
0	0	Even Byte	Odd Byte
1	0	Even Byte	-
0	1	_	Odd Byte



9.3.4.2 MC683XX and 68HC16

Figure 15 shows a Motorola MC68331 with non-multiplexed sixteen-bit data bus and 24-bit address bus. The data bus from the MC68331 is connected to Port F (D0-7) and Port G (D8-D15). The SIZ0 and A0 inputs determine the high/low byte selection. The R/W, DS and SIZ0 are connected to the CNTL0-2 pins.

The 68HC16 and other members of the 683XX family have the same connection as the 68331 shown in Figure 15.

9.3.4.3 80C51XA

The Philips 80C51XA microcontroller has a 16-bit multiplexed bus with burst cycles. Address bits A[3:1] are not multiplexed while A[19:4] are multiplexed with data bits D[15:0].

The PSD4135G2 supports the 80C51XA burst mode. The WRH signal is connected to the PD3 and the WRL is connected to CNTL0 pin. The RD and PSEN signal is connected to CNTL1-2 pins. Figure 15 shows the XA schematic.

The 80C51XA improves bus throughput and performance by issuing Burst cycles to fetch codes from memory. In Burst cycles, addresses A19-4 are latched internally by the PSD, while the 80C51XA drives the A3-1 lines to sequentially fetch up to 16 bytes of code. The PSD access time is then measured from address A3-A1 valid to data in valid. The PSD bus timing requirement in Burst cycle is identical to the normal bus cycle except the address set up or hold time with respect to ALE is not required.

9.3.4.4 H8/300

Figure 16 shows a Hitachi H8/2350 with non-multiplexed sixteen-bit data bus and 24-bit address bus. The H8 data bus is connected to Port F (D0-7) and Port G (D8-15). The WRL, WRH and RD signals are connected to the CNTL0, PD3 and CNTL1 pins respectively. The AS connection is optional and is required if the address are to be latched.

9.3.4.5 MMC2001

The Motorola MCORE MMC2001 microcontroller has a MOD input pin that selects internal or external boot ROM. The PSD4000 can be configured as the external flash boot ROM or as extension to the internal ROM.

The MMC2001 has a 16-bit external data bus and 20 address lines with external Chip Select signals. The Chip Select Control Registers allow the user to customize the bus interface and timing to fit the individual system requirement. A typical interface configuration to the PSD4000 is shown in Figure 18. The MMC2001's R/W signal is connected to the cntl0 pin, while EB0 and EB1 (enable byte0 and byte1) are connected to the cntl1 (UDS) and cntl2 (LDS) pins. The WEN bit in the Chip Select Control Register should set to 1 to terminate the EB[0:1] earlier to provide the write data hold time for the PSD. The WSC and WWS bits in the Control Register are set to wait states that meet the PSD access time requirement.

Another option is to configure the <u>EB0 and</u> <u>EB1</u> as WRL and WRH signals. In this case the PSD4000 control setting will be: OE, WRL, WRH where OE is the read signal from the MMC2001.

9.3.4.6 C16X Family

The PSD4000 supports Infineon's C16X family of microcontrollers (C161-C167) in both the multiplexed and non-multiplexed bus configuration. In Figure 19 the C167CR is shown connected to the PSD4000 in a multiplexed bus configuration. The control signals from the MCU are WR, RD, BHE and ALE and are routed to the corresponding PSD pins.

The C167 has another control signal setting (\overline{RD} , \overline{WRL} , \overline{WRH} , ALE) which is also supported by the PSD4000.



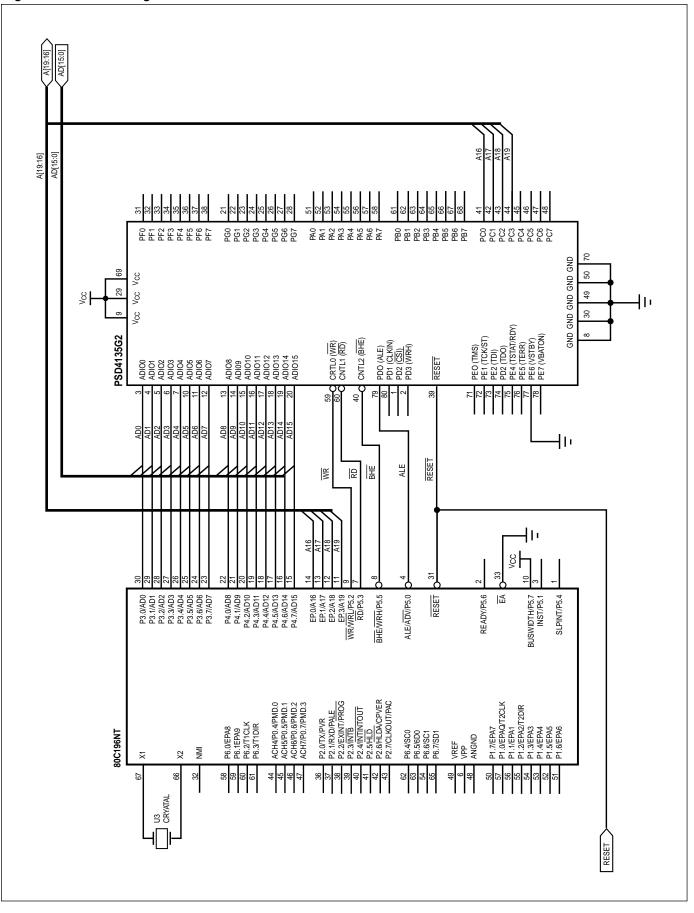
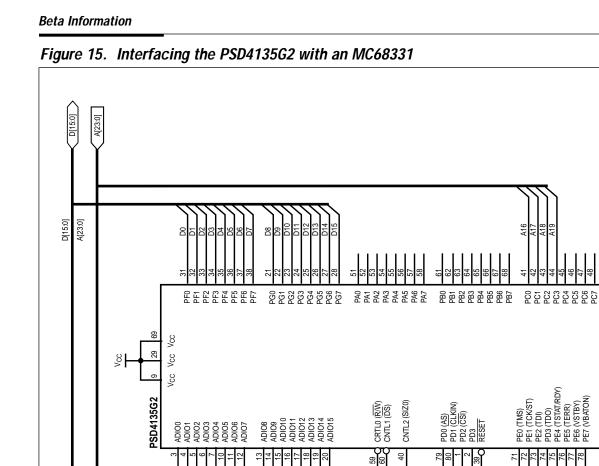


Figure 14. Interfacing the PSD4135G2 with an 80C196



A11 A11 A11

8

200

AO

6

MC68331

111

8

0262232200 042023222

D6 D2

A7 A5 A3 A3

AS

RESET

82 68

AS

RESET

20

SIZ0

DSACK0 DSACK1

88

u ji

80

SIZ1

90

CLKOUT

SIZ0

SO

R/W

20

50

49

8

œ

ا

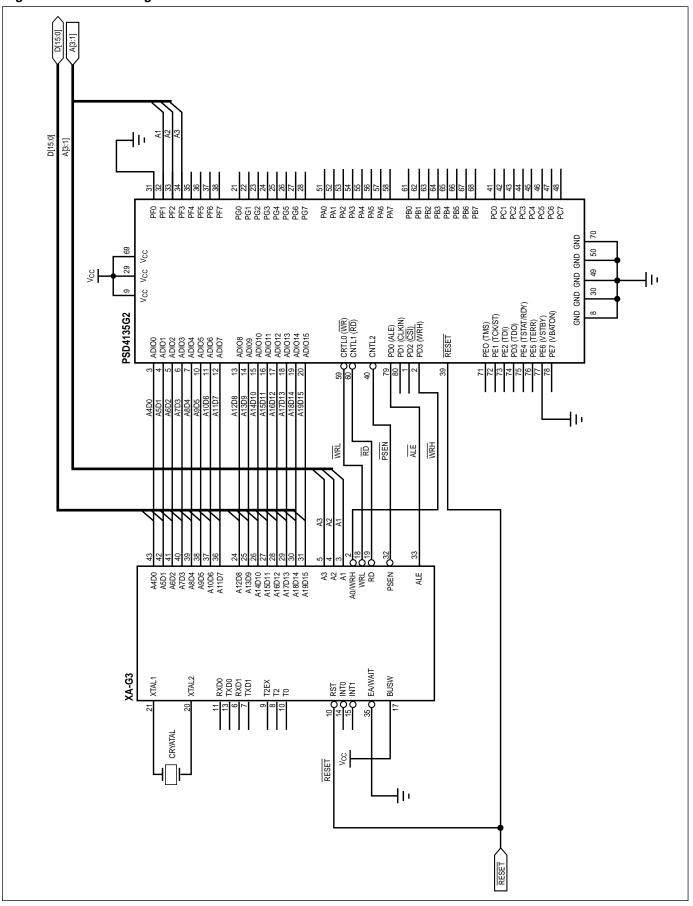
RESET

RESET

GND GND GND GND GND

1Γ

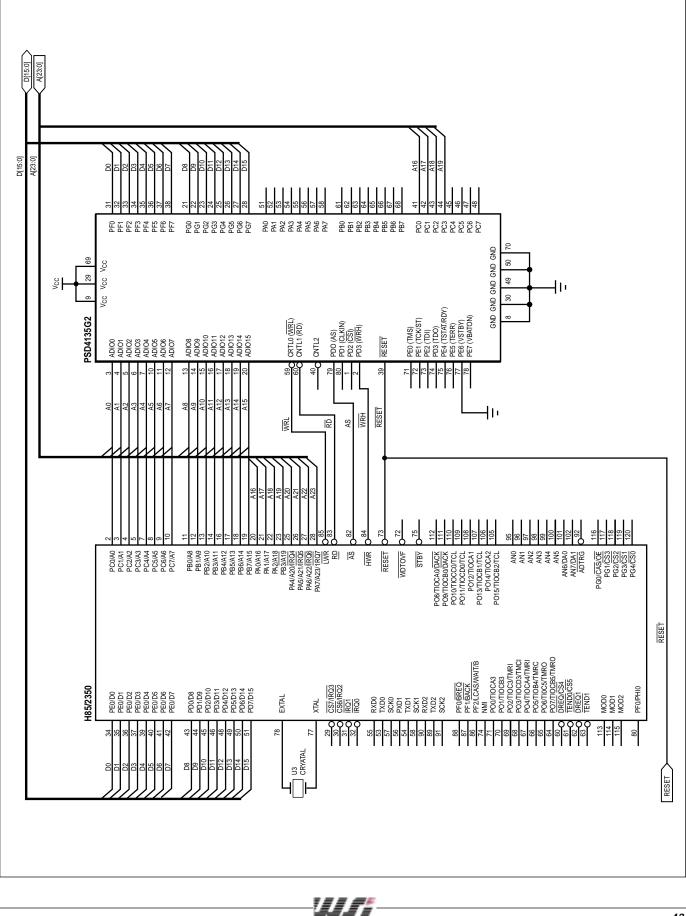
CSB00T BR_CS0 BGACK_CS2 FC0_CS3 FC1_CS4 FC1_CS4 FC2_CS5



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PSD4000 Series

Figure 17. Interfacing a PSD4135G2 with a H83/2350



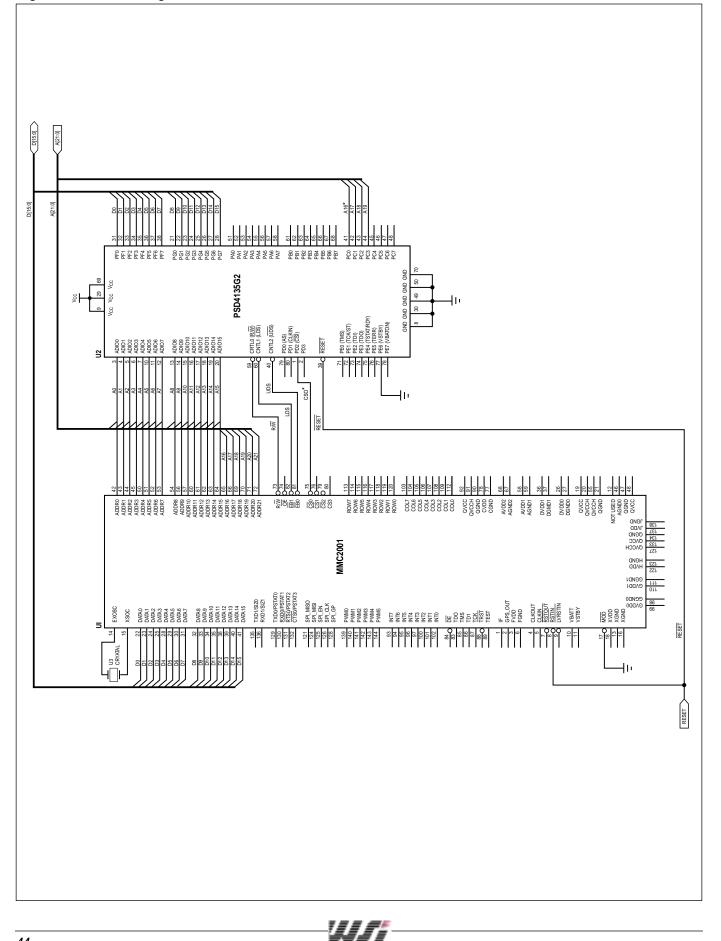
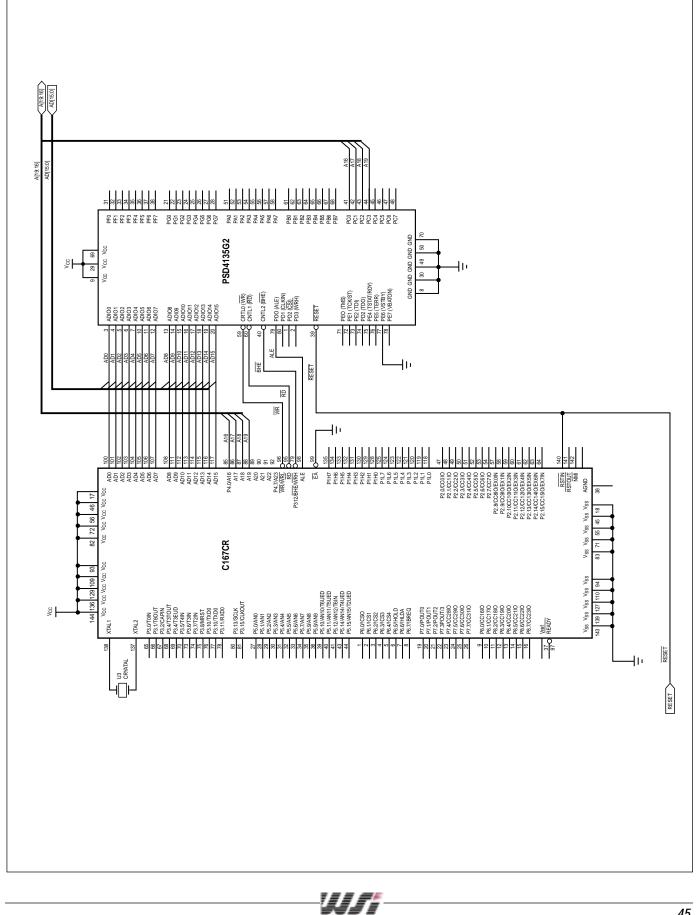


Figure 19. Interfacing a PSD4135G2 with a C167R



9.4 I/0 Ports

Beta Information

There are seven programmable I/O ports: Ports A, B, C, D, E, F and G. Each of the ports is eight bits except Port D, which is 4 bits. Each port pin is individually user configurable, thus allowing multiple functions per port. The ports are configured using PSDsoft or by the microcontroller writing to on-chip registers in the CSIOP address space.

The topics discussed in this section are:

- General Port Architecture
- Port Operating Modes
- Port Configuration Registers
- Port Data Registers
- Individual Port Functionality.

9.4.1 General Port Architecture

The general architecture of the I/O Port is shown in Figure 20. Individual Port architectures are shown in Figures 21 through 23. In general, once the purpose for a port pin has been defined, that pin will no longer be available for other purposes. Exceptions will be noted.

As shown in Figure 20, the ports contain an output multiplexer whose selects are driven by the configuration bits in the Control Registers (Ports E, F and G only) and PSDsoft Configuration. Inputs to the multiplexer include the following:

- □ Output data from the Data Out Register
- □ Latched address outputs
- GPLD outputs (External Chip Selects)

The Port Data Buffer (PDB) is a tri-state buffer that allows only one source at a time to be read. The PDB is connected to the Internal Data Bus for feedback and can be read by the microcontroller. The Data Out and Micro⇔Cell outputs, Direction and Control Registers, and port pin input are all connected to the PDB.

The contents of these registers can be altered by the microcontroller. The PDB feedback path allows the microcontroller to check the contents of the registers.

9.4.2 Port Operating Modes

The I/O Ports have several modes of operation. Some modes can be defined using PSDsoft, some by the microcontroller writing to the Registers in CSIOP space, and some by both. The modes that can only be defined using PSDsoft must be programmed into the device and cannot be changed unless the device is reprogrammed. The modes that can be changed by the microcontroller can be done so dynamically at run-time. The PLD I/O, Data Port, Address Input, and MCU Reset modes are the only modes that must be defined before programming the device. All other modes can be changed by the microcontroller at run-time.

Table 16 summarizes which modes are available on each port. Table 19 shows how and where the different modes are configured. Each of the port operating modes are described in the following subsections.



 Table 16.
 Port Operating Modes

Port Mode	Port A	Port B	Port C	Port D	Port E	Port F	Port G
MCU I/O	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PLD Outputs	Yes	Yes	Yes	No	No	No	No
PLD Inputs	Yes	Yes	Yes	Yes	No	Yes	No
Address Out	No	No	No	No	Yes (A7-0)	Yes (A7-0)	Yes (A7-0) or (A15-8)
Address In	Yes	Yes	Yes	Yes	No	Yes	No
Data Port	No	No	No	No	No	Yes	Yes
JTAG ISP	No	No	No	No	Yes	No	No
MCU Reset Mode*	No	No	No	No	No	Yes	Yes

*Available to Motorola 16-bit 683XX and HC16family of MCUs.

Figure 20. General I/O Port Architecture

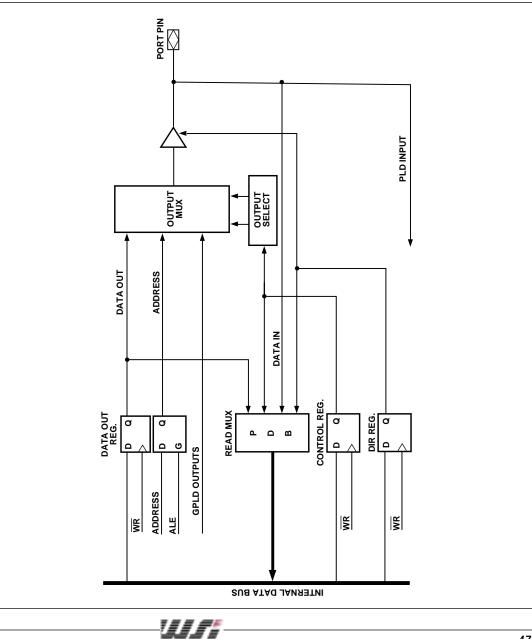


Table 17. Port Operating Mode Settings

	· · ·			
Mode	Defined In PSDsoft	Control Register Setting	Direction Register Setting	VM Register Setting
MCU I/O	Declare pins only	0 (Note 1)	1 = output, 0 = input	NA
PLD I/O	Declare pins and logic or chip select equations	NA		NA
Data Port (Port F, G)	Selected for MCU with non-mux bus	NA	NA	NA
Address Out (Port E, F, G)	Declare pins only	1	1	NA
Address In (Port A,B,C,D,F)	Declare pins	NA	NA	NA
JTAG ISP	Declare pins only	NA	NA	NA
MCU Reset Mode	Specify pin logic level	NA	NA	NA

*NA = Not Applicable

NOTE: 1. Control Register setting is not applicable to Ports A, B and C.

9.4.2.1 MCU I/O Mode

In the MCU I/O Mode, the microcontroller uses the PSD4000 ports to expand its own I/O ports. By setting up the CSIOP space, the ports on the PSD4000 are mapped into the microcontroller address space. The addresses of the ports are listed in Table 6.

A port pin can be put into MCU I/O mode by writing a '0' to the corresponding bit in the Control Register (Port E, F and G). The MCU I/O direction may be changed by writing to the corresponding bit in the Direction Register. See the subsection on the Direction Register in the "Port Registers" section. When the pin is configured as an output, the content of the Data Out Register drives the pin. When configured as an input, the microcontroller can read the port input through the Data In buffer. See Figure 20.

Ports A, B and C do not have Control Registers, and are in MCU I/O mode by default. They can be used for PLD I/O if they are specified in PSDsoft.

9.4.2.2 PLD I/O Mode

The PLD I/O Mode uses a port as an input to the CPLD's Input Micro⇔Cells, and/or as an output from the GPLD. The corresponding bit in the Direction Register must not be set to '1' if the pin is defined as a PLD input pin in PSDsoft. The PLD I/O Mode is specified in PSDsoft by declaring the port pins, and then specifying an equation in PSDsoft.



9.4.2.3 Address Out Mode

For microcontrollers with a multiplexed address/data bus, Address Out Mode can be used to drive latched addresses onto the port pins. These port pins can, in turn, drive external devices. Either the output enable or the corresponding bits of both the Direction Register and Control Register must be set to a '1' for pins to use Address Out Mode. This must be done by the MCU at run-time. See Table 18 for the address output pin assignments on Ports E, F and F for various MCUs.

Note: Do not drive address lines with Address Out Mode to an external memory device if it is intended for the MCU to boot from the external device. The MCU must first boot from PSD memory so the Direction and Control register bits can be set.

, , ,									
МСИ	Port E (3:0)	Port E (7:4)	Port F (3:0)	Port F (7:4)	Port G (3:0)	Port G (7:4)			
80C51XA	N/A	Addr (7:4)	N/A	Addr (7:4)	Addr (11:8)	Addr (15:12)			
All Other MCU with Multiplexed Bus	Addr (3:0)	Addr (7:4)	Addr (3:0)	Addr (7:4)	Addr (11:8)	Addr (15:12)			

 Table 18.
 I/O Port Latched Address Output Assignments

9.4.2.4 Address In Mode

For microcontrollers that have more than 16 address lines, the higher addresses can be connected to Ports A, B, C, D or F and are routed as inputs to the PLDs. The address input can be latched by the address strobe (ALE/AS). Any input that is included in the DPLD equations for the Main Flash, Boot Flash, or SRAM is considered to be an address input.

9.4.2.5 Data Port Mode

Port F and G can be used as a data bus port for a microcontroller with a non-multiplexed address/data bus. The Data Port is connected to the data bus of the microcontroller. The general I/O functions are disabled in Port F and G if the ports are configured as Data Port. Data Port Mode is automatically configured in PSDsoft when a non-multiplexed bus MCU is selected.

9.4.2.6 JTAG ISP

Port E is JTAG compliant, and can be used for In-System Programming (ISP).

9.4.2.7 MCU Reset Mode

Port F and G can be configured to operate in "MCU Reset" mode. This mode is available when PSD is configured for the Motorola 16-bit 683XX and HC16 family and is active only during reset.

At the rising edge of the Reset input, the MCU reads the logic level on the Data Bus D15-0 pins. The MCU then configures some of its I/O pin functions according to the logic level input on the data bus lines. Two dedicated buffers are usually enabled during reset to drive the data bus lines to the desired logic level.

The PSD4135G2 can replace the two buffers by configuring Port F and G to operate in MCU Reset Mode. In this mode, the PSD will drive the pre-defined logic level or data pattern onto the MCU Data Bus when reset is active and there is no ongoing bus cycle. After reset, Port F and G return to the normal Data Port Mode.

The MCU Reset Mode is enabled and configured in PSDsoft. The user defines the logic level (data pattern) that will be driven out from Port F and G during reset.



The

Blocks

(cont.)

9.4.3 Port Configuration Registers (PCRs)

Beta Information

Each port has a set of PCRs used for configuration. The contents of the registers can be accessed by the microcontroller through normal read/write bus cycles at the addresses given in Table 6. The addresses in Table 6 are the offsets in hex from the base of the CSIOP register.

The pins of a port are individually configurable and each bit in the register controls its respective pin. For example, Bit 0 in a register refers to Bit 0 of its port. The three PCRs, shown in Table 19, are used for setting the port configurations. The default power-up state for each register in Table 22 is 00h.

Register Name	Port	MCU Access
Control	E,F,G	Write/Read
Direction	A,B,C,D,E,F,G	Write/Read
Drive Select*	A,B,C,D,E,F,G	Write/Read

Table 19. Port Configuration Registers

*NOTE: See Table 22 for Drive Register bit definition.

9.4.3.1 Control Register

Any bit set to '0' in the Control Register sets the corresponding Port pin to MCU I/O Mode, and a '1' sets it to Address Out Mode. The default mode is MCU I/O. Only Ports E, F and G have an associated Control Register.

9.4.3.2 Direction Register

The Direction Register controls the direction of data flow in the I/O Ports. Any bit set to '1' in the Direction Register will cause the corresponding pin to be an output, and any bit set to '0' will cause it to be an input. The default mode for all port pins is input.

Figures 21 and 23 show the Port Architecture diagrams for Ports A/B/C and E/F/G respectively. The direction of data flow for Ports A, B, C and F are controlled by the direction register.

An example of a configuration for a port with the three least significant bits set to output and the remainder set to input is shown in Table 21. Since Port D only contains four pins, the Direction Register for Port D has only the four least significant bits active.

Table 20. Port Pin Direction Control

Direction Register Bit	Port Pin Mode
0	Input
1	Output

Table 21. Port Direction Assignment Example

[Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	0	0	0	0	0	1	1	1



9.4.3.3 Drive Select Register

The Drive Select Register configures the pin driver as Open Drain or CMOS for some port pins, and controls the slew rate for the other port pins. An external pull-up resistor should be used for pins configured as Open Drain.

A pin can be configured as Open Drain if its corresponding bit in the Drive Select Register is set to a '1'. The default pin drive is CMOS.

Aside: the slew rate is a measurement of the rise and fall times of an output. A higher slew rate means a faster output response and may create more electrical noise. A pin operates in a high slew rate when the corresponding bit in the Drive Register is set to '1'. The default rate is slow slew.

Table 22 shows the Drive Register for Ports A, B, C, D, E, F and G. It summarizes which pins can be configured as Open Drain outputs and which pins the slew rate can be set for.

Drive Register	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Port A	Open	Open	Open	Open	Open	Open	Open	Open
	Drain	Drain	Drain	Drain	Drain	Drain	Drain	Drain
Port B	Open	Open	Open	Open	Open	Open	Open	Open
	Drain	Drain	Drain	Drain	Drain	Drain	Drain	Drain
Port C	Slew	Slew	Slew	Slew	Slew	Slew	Slew	Slew
	Rate	Rate	Rate	Rate	Rate	Rate	Rate	Rate
Port D					Open Drain	Open Drain	Open Drain	Open Drain
Port E	Open	Open	Open	Open	Open	Open	Open	Open
	Drain	Drain	Drain	Drain	Drain	Drain	Drain	Drain
Port F	Slew	Slew	Slew	Slew	Slew	Slew	Slew	Slew
	Rate	Rate	Rate	Rate	Rate	Rate	Rate	Rate
Port G	Open	Open	Open	Open	Open	Open	Open	Open
	Drain	Drain	Drain	Drain	Drain	Drain	Drain	Drain

 Table 22. Drive Register Pin Assignment

9.4.4 Port Data Registers

The Port Data Registers, shown in Table 23, are used by the microcontroller to write data to or read data from the ports. Table 23 shows the register name, the ports having each register type, and microcontroller access for each register type. The registers are described below.

9.4.4.1 Data In

Port pins are connected directly to the Data In buffer. In MCU I/O input mode, the pin input is read through the Data In buffer.

9.4.4.2 Data Out Register

Stores output data written by the MCU in the MCU I/O output mode. The contents of the Register are driven out to the pins if the Direction Register or the output enable product term is set to "1". The contents of the register can also be read back by the microcontroller.

Table 27. Port Data Registers

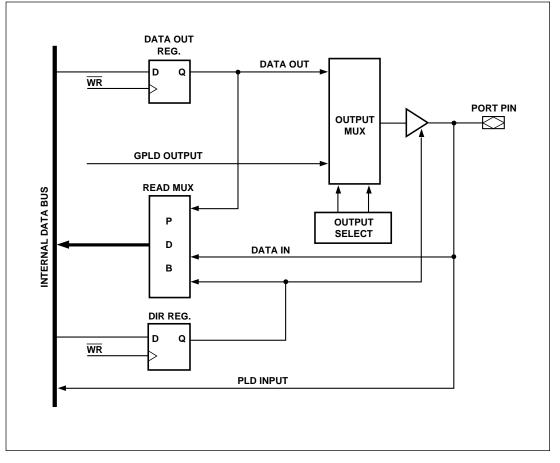
Register Name	Port	MCU Access
Data In	A,B,C,D,E,F,G	Read – input on pin
Data Out	A,B,C,D,E,F,G	Write/Read



The
PSD40009.4.5 Ports A, B and C - Functionality and StructurePsD4000Ports A and B have similar functionality and structure, as shown in Figure 21. The two
ports can be configured to perform one or more of the following functions:BlocksImage: MCU I/O Mode(cont.)Image: GPLD Output - Combinatorial PLD outputs.

- □ PLD Input Input to the PLDs.
- □ Address In Additional high address inputs may be latched by ALE.
- Open Drain/Slew Rate pins PC[7:0]can be configured to fast slew rate, pins PA[7:0] and PB[7:0] can be configured to Open Drain Mode.







The	9.4.6 Port D – Functionality and Structure
PSD4000	Port D has four I/O pins. See Figure 22. Port D can be configured to program one or more
Functional	of the following functions:
Blocks	MCU I/O Mode
(cont.)	PLD Input – direct input to PLD

Port D pins can be configured in PSDsoft as input pins for other dedicated functions:

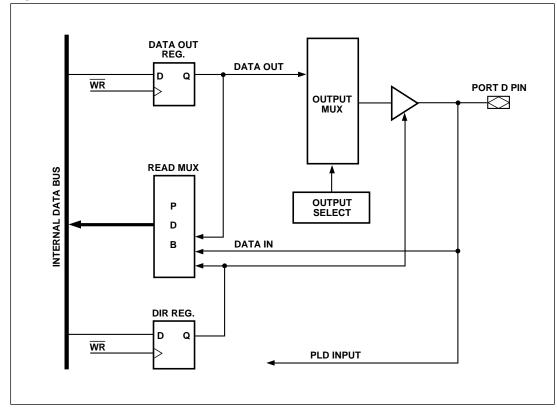
- □ PD0 ALE, as address strobe input
- □ PD1 CLKIN, as clock input to the PLD and APD counter
- □ PD2 CSI, as active low chip select input. A high input will disable the Flash/SRAM and CSIOP.
- PD3 WRH, as active low Write Enable (high byte) input or as DBE input from 68HC912

9.4.7 Port E – Functionality and Structure

Port E can be configured to perform one or more of the following functions (see Figure 23):

- □ MCU I/O Mode
- □ In-System Programming JTAG port can be enabled for programming/erase of the PSD4000 device. (See Section 9.6 for more information on JTAG programming.) Pins that are configured as JTAG pins in PSDsoft will not be available for other I/O functions.
- □ Open Drain Port E pins can be configured in Open Drain Mode
- Battery Backup features PE6 can be configured as a Battery Input (Vstby) pin. PE7 can be configured as a Battery On Indicator output pin, indicating when Vcc is less than Vbat.
- □ Latched Address Output Provided latched address (A7-0) output

Figure 22. Port D Structure





The
PSD40009.4.8 Port F - Functionality and Structure
Port F can be configured to perform one or more of the following functions:Functional
Blocks
(cont.)MCU I/O Mode□MCU I/O Mode□PLD Input - as direct input of the PLD array.□Address In - additional high address inputs. Direct input to the PLD array.

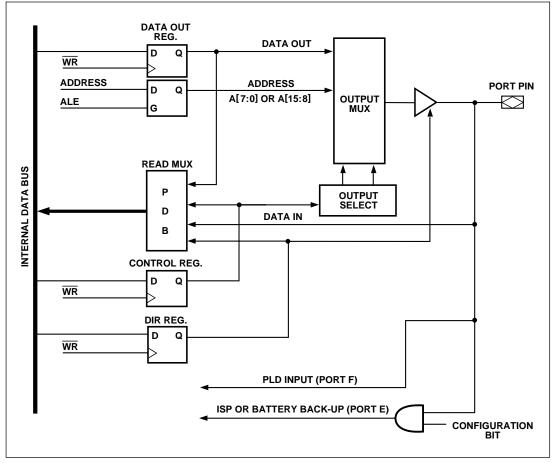
- Latched Address Out Provide latched address out per Table 29.
- □ Slew Rate pins can be set up for fast slew rate.
- □ Data Port connected to D[7:0] when Port F is configured as Data Port for a non-multiplexed bus.
- □ MCU Reset Mode for 16-bit Motorola 683XX and HC16 microcontrollers.

9.4.9 Port G – Functionality and Structure

Port G can be configured to perform one or more of the following functions:

- MCU I/O Mode
- □ Latched Address Out provide latched address out per Table 29.
- □ Open Drain pins can be configured in Open Drain Mode
- □ Data Port connected to D[15:8] when Port G is configured as Data Port for a non-multiplexed bus.
- □ MCU Reset Mode for 16-bit Motorola 683XX and HC16 microcontrollers







The PSD4000 Functional	9.5 Power Management The PSD4000 offers configurable power saving options. These options may be used individually or in combinations, as follows:
Blocks (cont.)	□ All memory types in a PSD (Flash, Secondary Flash, and SRAM) are built with Zero-Power technology. In addition to using special silicon design methodology, Zero-Power technology puts the memories into standby mode when address/data inputs are not changing (zero DC current). As soon as a transition occurs on an input, the affected memory "wakes up", changes and latches its outputs, then goes back to standby. The designer does not have to do anything special to achieve memory standby mode when no inputs are changing—it happens automatically.
	The PLD sections can also achieve standby mode when its inputs are not changing, see PMMR registers below.
	Like the Zero-Power feature, the Automatic Power Down (APD) logic allows the PSD to reduce to standby current automatically. The APD will block MCU address/data signals from reaching the memories and PLDs. This feature is available on all PSD4000 devices. The APD unit is described in more detail in section 9.5.1.
	Built in logic will monitor the address strobe of the MCU for activity. If there is no activity for a certain time period (MCU is asleep), the APD logic initiates Power Down Mode (if enabled). Once in Power Down Mode, all address/data signals are blocked from reaching PSD memories and PLDs, and the memories are deselected internally. This allows the memories and PLDs to remain in standby mode even if the address/data lines are changing state externally (noise, other devices on the MCU bus, etc.). Keep in mind that any unblocked PLD input signals that are changing states keeps the PLD out of standby mode, but not the memories.
	❑ The PSD Chip Select Input (CSI) can be used to disable the internal memories, placing them in standby mode even if inputs are changing. This feature does not block any internal signals or disable the PLDs. This is a good alternative to using the APD logic, especially if your MCU has a chip select output. There is a slight penalty in memory access time when the CSI signal makes its initial transition from deselected to selected.
	The PMMR registers can be written by the MCU at run-time to manage power. All PSD devices support "blocking bits" in these registers that are set to block designated signals from reaching both PLDs. Current consumption of the PLDs is directly related to the composite frequency of the changes on their inputs (see Figures 27 and 27a). Significant power savings can be achieved by blocking signals that are not used in PLD logic equations at run time. PSDsoft creates a fuse map that automatically blocks the low address byte (A7-A0) or the control signals (CNTL0-2, ALE and WRH/DBE) if none of these signals are used in PLD logic equations.
	The PSD4000 devices have a Turbo Bit in the PMMR0 register. This bit can be set to disable the Turbo Mode feature (default is Turbo Mode on). While Turbo Mode is disabled, the PLDs can achieve standby current when no PLD inputs are changing (zero DC current). Even when inputs do change, significant power can be saved at lower frequencies (AC current), compared to when Turbo Mode is enabled. Conversely, when the Turbo Mode is enabled, there is a significant DC current component and the AC component is higher.

9.5.1 Automatic Power Down (APD) Unit and Power Down Mode

The APD Unit, shown in Figure 24, puts the PSD into Power Down Mode by monitoring the activity of the address strobe (ALE/AS). If the APD unit is enabled, as soon as activity on the address strobe stops, a four bit counter starts counting. If the address strobe remains inactive for fifteen clock periods of the CLKIN signal, the Power Down (PDN) signal becomes active, and the PSD will enter into Power Down Mode, discussed next.



9.5.1 Automatic Power Down (APD) Unit and Power Down Mode (cont.)

Power Down Mode

By default, if you enable the PSD APD unit, Power Down Mode is automatically enabled. The device will enter Power Down Mode if the address strobe (ALE/AS) remains inactive for fifteen CLKIN (pin PD1) clock periods.

The following should be kept in mind when the PSD is in Power Down Mode:

- If the address strobe starts pulsing again, the PSD will return to normal operation. The PSD will also return to normal operation if either the CSI input returns low or the Reset input returns high.
- The MCU address/data bus is blocked from all memories and PLDs.
- Various signals can be blocked (prior to Power Down Mode) from entering the PLDs by setting the appropriate bits in the PMMR registers. The blocked signals include MCU control signals and the common clock (CLKIN). Note that blocking CLKIN from the PLDs will not block CLKIN from the APD unit.
- All PSD memories enter Standby Mode and are drawing standby current. However, the PLDs and I/O ports do **not** go into Standby Mode because you don't want to have to wait for the logic and I/O to "wake-up" before their outputs can change. See Table 24 for Power Down Mode effects on PSD ports.
- Typical standby current is 50 μ A for 5 V parts. This standby current value assumes that there are no transitions on any PLD input.

Table 24. Power Down Mode's Effect on Ports

Port Function	Pin Level
MCU I/O	No Change
PLD Out	No Change
Address Out	Undefined
Data Port	Three-State
Peripheral I/O	Three-State

Table 25. PSD4000 Timing and Standby Current During Power Down Mode

Mode	PLD Propagation Delay	Memory Access Time	Access Recovery Time to Normal Access	5V V _{CC} , Typical Standby Current
Power Down	Normal tpd (Note 1)	No Access	tLVDV	50 μA (Note 2)

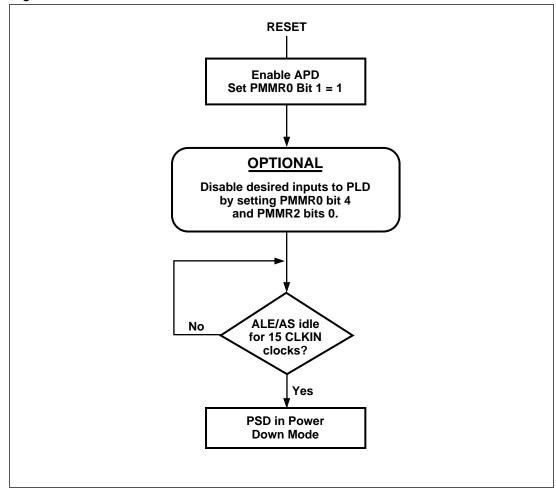
NOTES: 1. Power Down does not affect the operation of the PLD. The PLD operation in this mode is based only on the Turbo Bit.

2. Typical current consumption assuming no PLD inputs are changing state and the PLD Turbo bit is off.



The Figure 24. APD Logic Block **PSD4000** Functional APD EN PMMR0 BIT 1=1 **Blocks** (cont.) TRANSITION DETECTION DISABLE BUS ALE PD CLR SECONDARY FLASH SELECT APD COUNTER RESET MAIN FLASH SELECT EDGE PD CSI DETECT PLD SRAM SELECT POWER DOWN (PDN) SELECT **DISABLE MAIN AND** SECONDARY FLASH/SRAM

Figure 25. Enable Power Down Flow Chart



us

Table 26.	Power Management Mode Registers (PMMR0,	PMMR2)**
PMMR0		

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
*	*	*	PLD Array clk	PLD Turbo	*	APD Enable	*
			1 = off	1 = off		1 = on	

*Bits 0, 2, 6, and 7 are not used, and should be set to 0, bit 5 should be set to 1.

**The PMMR0, and PMMR2 register bits are cleared to zero following power up. Subsequent reset pulses will not clear the registers.

- Bit 1 0 = Automatic Power Down (APD) is disabled.
 - 1 = Automatic Power Down (APD) is enabled.
- Bit 3 0 = PLD Turbo is on.
 - 1 = PLD Turbo is off, saving power.
- Bit 4 0 = CLKIN input to the PLD AND array is connected.
 - Every CLKIN change will power up the PLD when Turbo bit is off.
 - 1 = CLKIN input to PLD AND array is disconnected, saving power.

PMMR2

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
*	PLD array WRH/DBE	PLD array ALE	PLD** array CNTL2	PLD** array CNTL1	PLD** array CNTL0	*	PLD array Addr.
	1 = off	1 = off	1 = off	1 = off	1 = off		1 = off

*Unused bits should be set to 0.

**Refer to Table 14 the signals that are blocked on pins CNTL0-2.

- Bit 0 0 = Address A[7:0] inputs to the PLD AND array are connected.
 - 1 = Address A[7:0] inputs to the PLD AND array are disconnected, saving power.
 Note: In 80C51XA mode, A[7:1] comes from Port F (PF1-PF3) and AD10 [3:0].
- Bit 2 0 = Cntl0 input to the PLD AND array is connected.
 - 1 = Cntl0 input to PLD AND array is disconnected, saving power.
- Bit 3 0 = Cntl1 input to the PLD AND array is connected.
 - 1 = Cntl1 input to PLD AND array is disconnected, saving power.
- Bit 4 0 = Cntl2 input to the PLD AND array is connected.
 - 1 = Cntl2 input to PLD AND array is disconnected, saving power.
- Bit 5 0 = ALE input to the PLD AND array is connected.
 - 1 = ALE input to PLD AND array is disconnected, saving power.
- Bit 6 0 = WRH/DBE input to the PLD AND array is connected.
 - 1 = WRH/DBE input to PLD AND array is disconnected, saving power.



Table 27. APD Counter Operation

APD Enable Bit	ALE PD Polarity	ALE Level	APD Counter
0	Х	Х	Not Counting
1	Х	Pulsing	Not Counting
1	1	1	Counting (Generates PDN after 15 Clocks)
1	0	0	Counting (Generates PDN after 15 Clocks)

9.5.2 Other Power Saving Options

The PSD4000 offers other reduced power saving options that are independent of the Power Down Mode. Except for the SRAM Standby and CSI input features, they are enabled by setting bits in the PMMR0 and PMMR2 registers.

9.5.2.1 Zero Power PLD

The power and speed of the PLDs are controlled by the Turbo bit (bit 3) in the PMMR0. By setting the bit to "1", the Turbo mode is disabled and the PLDs consume Zero Power current when the inputs are not switching for an extended time of 70 ns. The propagation delay time will be increased after the Turbo bit is set to "1" (turned off) when the inputs change at a composite frequency of less than 15 MHz. When the Turbo bit is set to a "0" (turned on), the PLDs run at full power and speed. The Turbo bit affects the PLD's D.C. power, AC power, and propagation delay. Refer to AC/DC spec for PLD timings.

Note: Blocking MCU control signals with PMMR2 bits can further reduce PLD AC power consumption.

9.5.2.2 SRAM Standby Mode (Battery Backup)

The PSD4000 supports a battery backup operation that retains the contents of the SRAM in the event of a power loss. The SRAM has a Vstby pin (PE6) that can be connected to an external battery. When V_{CC} becomes lower than Vstby then the PSD will automatically connect to Vstby as a power source to the SRAM. The SRAM Standby Current (Istby) is typically 0.5 μ A. The SRAM data retention voltage is 2 V minimum. The battery-on indicator (Vbaton) can be routed to PE7. This signal indicates when the V_{CC} has dropped below the Vstby voltage and that the SRAM is running on battery power.

9.5.2.3 The CSI Input

Pin PD2 of Port D can be configured in PSDsoft as the CSI input. When low, the signal selects and enables the internal Flash, Boot Block, SRAM, and I/O for read or write operations involving the PSD4000. A high on the CSI pin will disable the Flash memory, Boot Block, and SRAM, and reduce the PSD power consumption. However, the PLD and I/O pins remain operational when CSI is high. **Note:** there may be a timing penalty when using the CSI pin depending on the speed grade of the PSD that you are using. See the timing parameter t_{SLQV} in the AC/DC specs.

9.5.2.4 Input Clock

The PSD4000 provides the option to turn off the CLKIN input to the PLD AND array to save AC power consumption. During Power Down Mode, or, if the CLKIN input is not being used as part of the PLD logic equation, the clock should be disabled to save AC power. The CLKIN will be disconnected from the PLD AND array by setting bit 4 to a "1" in PMMR0.

9.5.2.5 MCU Control Signals

The PSD4000 provides the option to turn off the address input (A7-0) and input control signals (CNTL0-2, ALE, and WRH/DBE) to the PLD to save AC power consumption. These signals are inputs to the PLD AND array. During Power Down Mode, or, if any of them are not being used as part of the PLD logic equation, these control signals should be disabled to save AC power. They will be disconnected from the PLD AND array by setting bits 0, 2, 3, 4, 5, and 6 to a "1" in the PMMR2.



9.5.3 Reset and Power On Requirement

9.5.3.1 Power On Reset

Upon power up the PSD4000 requires a reset pulse of tNLNH-PO (minimum 1 ms) after V_{CC} is steady. During this time period the device loads internal configurations, clears some of the registers and sets the Flash into operating mode. After the rising edge of reset, the PSD4000 remains in the reset state for an additional tOPR (maximum 120 ns) nanoseconds before the first memory access is allowed.

The PSD4000 Flash memory is reset to the read array mode upon power up. The FSi and CSBOOTi select signals along with the write strobe signal must be in the false state during power-up reset for maximum security of the data contents and to remove the possibility of data being written on the first edge of a write strobe signal. Any Flash memory write cycle initiation is prevented automatically when V_{CC} is below VLKO.

9.5.3.2 Warm Reset

Once the device is up and running, the device can be reset with a much shorter pulse of tNLNH (minimum 150 ns). The same tOPR time is needed before the device is operational after warm reset. Figure 26 shows the timing of the power on and warm reset.

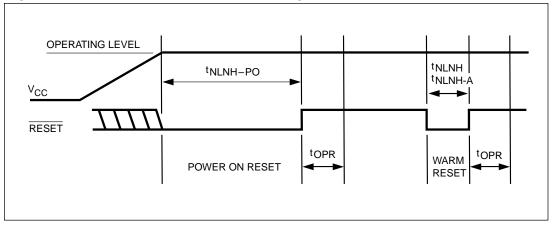


Figure 26. Power On and Warm Reset Timing

9.5.3.3 I/O Pin, Register and PLD Status at Reset

Table 28 shows the I/O pin, register and PLD status during power on reset, warm reset and power down mode. PLD outputs are always valid during warm reset, and they are valid in power on reset once the internal PSD configuration bits are loaded. This loading of PSD is completed typically long before the V_{CC} ramps up to operating level. Once the PLD is active, the state of the outputs are determined by the equations specified in PSDsoft.



Table 28. Status During Power On Reset, Warm Reset and Power Down Mode

Port Configuration	Power On Reset	Warm Reset	Power Down Mode
MCU I/O	Input Mode	Input Mode	Unchanged
PLD Output	Valid after internal PSD configuration bits are loaded	Valid	Depend on inputs to PLD (address are blocked in PD mode)
Address Out	Tri-stated	Tri-stated	Not defined
Data Port	Tri-stated	Tri-stated	Tri-stated

Register	Power On Reset	Warm Reset	Power Down Mode
PMMR0, 2	Cleared to "0"	Unchanged	Unchanged
VM Register*	Initialized based on the selection in PSDsoft Configuration Menu.	Initialized based on the selection in PSDsoft Configuration Menu.	Unchanged
All other registers	Cleared to "0"	Cleared to "0"	Unchanged

*SR_cod bit in the VM Register are always cleared to zero on power on or warm reset.

9.5.3.4 Reset of Flash Erase and Programming Cycles

An external reset on the RESET pin will also reset the internal Flash memory state machine. When the Flash is in programming or erase mode, the RESET pin will terminate the programming or erase operation and return the Flash back to read mode in tNLNH-A (minimum 25 μ s) time.

9.6 Programming In-Circuit using the JTAG-ISP Interface

The JTAG-ISP interface on the PSD4000 can be enabled on Port E (see Table 29). All memory (Flash and Flash Boot Block), PLD logic, and PSD configuration bits may be programmed through the JTAG-ISC interface. A blank part can be mounted on a printed circuit board and programmed using JTAG-ISP.

The standard JTAG signals (IEEE 1149.1) are TMS, TCK, TDI, and TDO. Two additional signals, TSTAT and TERR, are optional JTAG extensions used to speed up program and erase operations.

By default, on a blank PSD (as shipped from factory or after erasure), four pins on Port E are enabled for the basic JTAG signals TMS, TCK, TDI, and TDO.

See Waferscale Application Note 54 for more details on JTAG In-System-Programming.

Port E Pin	JTAG Signals	Description				
PE0	TMS	Mode Select				
PE1	ТСК	Clock				
PE2	TDI	Serial Data In				
PE3	TDO	Serial Data Out				
PE4	TSTAT	Status				
PE5	TERR	Error Flag				

 Table 29. JTAG Port Signals



9.6.1 Standard JTAG Signals

The JTAG configuration bit (non-volatile) inside the PSD can be set by the user in the PSDsoft. Once this bit is set and programmed in the PSD, the JTAG pins are dedicated to JTAG at all times and is in compliance with IEEE 1149.1. After power up the standard JTAG signals (TDI, TDO TCK and TMS) are inputs, waiting for a serial command from an external JTAG controller device (such as FlashLink or Automated Test Equipment). When the enabling command is received from the external JTAG controller, TDO becomes an output and the JTAG channel is fully functional inside the PSD. The same command that enables the JTAG channel may optionally enable the two additional JTAG pins, TSTAT and TERR.

Beta Information

The PSD4000 supports JTAG ISP commands, but not Boundary Scan. Waferscale's PSDsoft software tool and FlashLink JTAG programming cable implement these JTAG-ISP commands.

9.6.2 JTAG Extensions

TSTAT and TERR are two JTAG extension signals enabled by a JTAG command received over the four standard JTAG pins (TMS, TCK, TDI, and TDO). They are used to speed programming and erase functions by indicating status on PSD pins instead of having to scan the status out serially using the standard JTAG channel. See Application Note 54.

TERR will indicate if an error has occurred when erasing a sector or programming a byte in Flash memory. This signal will go low (active) when an error condition occurs, and stay low until a special JTAG command is executed or a chip reset pulse is received after an "ISC-DISABLE" command.

TSTAT behaves the same as the Rdy/Bsy signal described in section 9.1.1.2. TSTAT will be high when the PSD4000 device is in read array mode (Flash memory and Boot Block contents can be read). TSTAT will be low when Flash memory programming or erase cycles are in progress, and also when data is being written to the Secondary Flash Block.

TSTAT and TERR can be configured as open-drain type signals with a JTAG command.

9.6.3 Security and Flash Memories Protection

When the security bit is set, the device cannot be read on a device programmer or through the JTAG Port. When using the JTAG Port, only a full chip erase command is allowed. All other program/erase/verify commands are blocked. Full chip erase returns the part to a non-secured blank state. The Security Bit can be set in PSDsoft.

All Flash Memory and Boot sectors can individually be sector protected against erasures. The sector protect bits can be set in PSDsoft.



10.0 Absolute Maximum Ratings

Symbol	Parameter	Condition	Min	Max	Unit	
T _{STG}	Storage Temperature	PLDCC	- 65	+ 125	°C	
	Operating Temperature	Commercial	0	+ 70	°C	
	Operating Temperature	Industrial	- 40	+ 85	°C	
	Voltage on any Pin	With Respect to GND	- 0.6	+ 7	V	
V _{PP}	Device Programmer Supply Voltage	With Respect to GND	- 0.6	+ 14	V	
V _{CC}	Supply Voltage	With Respect to GND	- 0.6	+ 7	V	
	ESD Protection		>2000		V	

NOTE: Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not recommended. Exposure to Absolute Maximum Rating conditions for extended periods of time may affect device reliability.

11.0 Operating Range	Range	Temperature	V _{CC} Tolerance
	Commercial	0° C to +70°C	+ 5 V ± 10%
nunge	Industrial	–40° C to +85°C	+ 5 V ± 10%
	Commercial	0° C to +70°C	3.0 V to 3.6 V
	Industrial	-40° C to +85°C	3.0 V to 3.6 V

12.0 Recommended	Symbol	Parameter	Condition	Min	Тур	Max	Unit
Operating	V _{CC}	Supply Voltage	All Speeds	4.5	5	5.5	V
Conditions	V _{CC}	Supply Voltage	V-Versions All Speeds	3.0		3.6	V



AC/DC Parameters

The following tables describe the AD/DC parameters of the PSD4000 family:

DC Electrical Specification

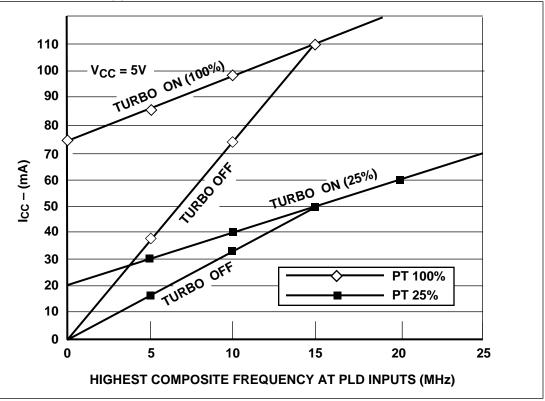
- □ AC Timing Specification
 - PLD Timing
 - Combinatorial Timing
 - Microcontroller Timing
 - Read Timing
 - Write Timing
 - Power Down and Reset Timing

Following are issues concerning the parameters presented:

- □ In the DC specification the supply current is given for different modes of operation. Before calculating the total power consumption, determine the percentage of time that the PSD4000 is in each mode. Also, the supply power is considerably different if the Turbo bit is "OFF".
- □ The AC power component gives the PLD, Flash memory, and SRAM mA/MHz specification. Figures 27 and 27a show the PLD mA/MHz as a function of the number of Product Terms (PT) used.
- □ In the PLD timing parameters, add the required delay when Turbo bit is "OFF".

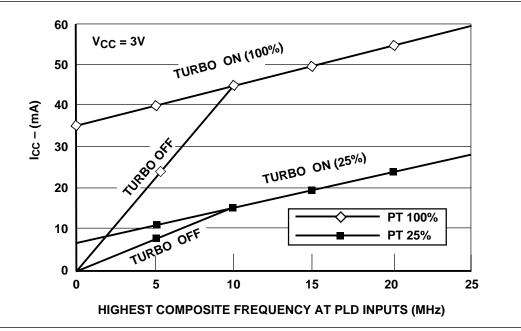


J



AC/DC Parameters (cont.)





Example of PSD4000 Typical Power Calculation at $V_{CC} = 5.0 V$

wji

Conditions		
Highest Composite PLD input frequency (Freq PLD)		8 MHz
MCU ALE frequency (Freq ALE)	=	4 MHz
% Flash Access	=	80%
% SRAM access		15%
% I/O access	=	5% (no additional power above base)
Operational Modes		4.00/
% Normal % Power Down Mode		10% 90%
,	=	90%
Number of product terms used	_	45 PT
(from fitter report) % of total product terms		45/176 = 25.5%
Turbo Mode		ON
Calculation (typical numbers used)		
+ %SRAM x 1.5 mA + % PLD x 2 mA/M + #PT x 400 μA/PT	norm \/MH Hz >	hal x (%flash x 2.5 mA/MHz x Freq ALE Hz x Freq ALE < Freq PLD
= 50 μA x 0.90 + 0.1 x (0.8 x 2. + 0.15 x 1.5 mA/MH +2 mA/MHz x 8 MH + 45 x 0.4 mA/PT)	Ιz x	
= 45 μA + 0.1 x (8 + 0.9 + 16 + = 45 μA + 0.1 x 42.9 = 45 μA + 4.29 mA	18	mA)
= 4.34 mA		
This is the operating power with no Flash on $I_{OUT} = 0$ mA.	wri	tes or erases. Calculation is based

AC/DC Parameters (cont.)	Example of Typical Power Calculation at V _{CC} = 5.0 V in Turbo Off Mode Conditions					
	Highest Composite PLD input freque (Freq PLD)	ncy = 8 MHz				
	MCU ALE frequency (Freq ALE)	= 4 MHz				
	% Flash Access % SRAM access	= 80% = 15%				
	% I/O access	= 5% (no additional power above base)				
	Operational Modes % Normal	= 10%				
	% Power Down Mode	= 90%				
	Number of product terms used					
	(from fitter report)	= 45 PT				
	% of total product terms	= 45/176 = 25.5%				
	Turbo Mode	= Off				
	Calculation (typical numbers used)					
	I _{CC} total = Ipwrdown x %pwrdown + %normal x (I _{CC} (ac) + I _{CC} (dc)) = Ipwrdown x %pwrdown + % normal x (%flash x 2.5 mA/MHz x Freq ALE + %SRAM x 1.5 mA/MHz x Freq ALE + % PLD x (from graph using Freq PLD))					
	= 50 μA x 0.90 + 0.1 x (0.8 x 2.5 mA/MHz x 4 MHz + 0.15 x 1.5 mA/MHz x 4 MHz + 24 mA)					
	$= 45 \mu\text{A} + 0.1 \text{x} (8 + 0.9 + 24)$					
	$= 45 \mu\text{A} + 0.1 \text{x} 32.9$					
	$= 45 \mu\text{A} + 3.29 \text{mA}$					
	= 3.34 mA					
	This is the operating power with no F on $I_{OUT} = 0$ mA.	lash writes or erases. Calculation is based				

on $I_{OUT} = 0$ mA.



PSD4000 DC Characteristics (5 V ± 10% Versions)

Symbol	Parameter		Conditions	Min	Тур	Max	Unit
V _{CC}	Supply Voltage		All Speeds	4.5	5	5.5	V
V _{IH}	High Level Input Voltage		4.5 V < V _{CC} < 5.5 V	2		V _{CC} +.5	V
V _{IL}	Low Level Input Voltage		4.5 V < V _{CC} < 5.5 V	5		0.8	V
V _{IH1}	Reset High Level Input Voltage		(Note 1)	.8 V _{CC}		V _{CC} +.5	V
V _{IL1}	Reset Low Level Inp	ut Voltage	(Note 1)	5		.2 V _{CC} –.1	V
V _{HYS}	Reset Pin Hysteresis	3		0.3			V
V _{LKO}	V _{CC} Min for Flash Era	ase and Program		2.5		4.2	V
V _{OL}	Output Low Voltage		$I_{OL} = 20 \ \mu A, V_{CC} = 4.5 \ V$		0.01	0.1	V
νOL			I _{OL} = 8 mA, V _{CC} = 4.5 V		0.25	0.45	V
V _{OH}	Output High Voltage Except V _{STBY} On		$I_{OH} = -20 \ \mu A, \ V_{CC} = 4.5 \ V$	4.4	4.49		V
∙он			$I_{OH} = -2 \text{ mA}, V_{CC} = 4.5 \text{ V}$	2.4	3.9		V
V _{OH1}	Output High Voltage V _{STBY} On		I _{OH1} = −1 μA	V _{SBY} - 0.8			V
V _{SBY}	SRAM Standby Voltage			2.0		V _{CC}	V
I _{SBY}	SRAM Standby Current (V _{STBY} Pin)		$V_{CC} = 0 V$		0.5	1	μA
I _{IDLE}	Idle Current (V _{STBY} Pin)		$V_{CC} > V_{SBY}$	-0.1		0.1	μA
V _{DF}	SRAM Data Retention Voltage		Only on V _{STBY}	2			V
I _{SB}	Standby Supply Current for Power Down Mode		CSI > V _{CC} –0.3 V (Notes 2, 3 and 5)		100	200	μA
ILI	Input Leakage Current		$V_{SS} < V_{IN} < V_{CC}$	-1	±.1	1	μA
I _{LO}	Output Leakage Current		0.45 < V _{IN} < V _{CC}	-10	±5	10	μA
I _O	Output Current		Refer to I_{OL} and I_{OH} in the V_{OL} and V_{OH} row				
I _{CC} (DC)	Operating Supply Current	PLD Only	PLD_TURBO = OFF, f = 0 MHz (Note 3)		0		mA
			PLD_TURBO = ON, f = 0 MHz		400	700	µA/PT
(Note 5)		Flash	During Flash Write/Erase Only		15	30	mA
			Read Only, f = 0 MHz		0	0	mA
		SRAM	f = 0 MHz		0	0	mA
I _{CC} (AC)	PLD AC Base			Fig. 27 (Note 4)			
(Note 5)	FLASH AC Adder		I		2.5	3.5	mA/MH
· -/	SRAM AC Adder				1.5	3.0	mA/MH

NOTE: 1. Reset input has hysteresis. V_{IL1} is valid at or below .2V_{CC} -.1. V_{IH1} is valid at or above .8V_{CC}.
2. CSI deselected or internal Power Down mode is active.

3. PLD is in non-turbo mode and none of the inputs are switching

4. Refer to Figure 32 for PLD current calculation.

5. $I_0 = 0 \text{ mA}$



AC Symbols for PLD Timing. Microcontroller Interface -Example: t_{AVLX} – Time from Address Valid to ALE Invalid. AC/DC **Parameters** Signal Letters (5V ± 10% Versions) A - Address Input

- C CEout Output
- D Input Data
- E E Input
- I Interrupt Input
- L ALE Input
- N Reset Input or Output
- P Port Signal Output
- R UDS, LDS, DS, RD, PSEN Inputs
- S Chip Select Input
- T R/W Input
- W WR Input
- B Vstby Output
- M Output Micro⇔Cell

Signal Behavior

- Time t
- L Logic Level Low or ALE
- H Logic Level High
- V Valid
- X No Longer a Valid Logic Level
- Float Ζ
- PW Pulse Width



(5V ± 10% Versions)

Read Timing (5 V ± 10% Versions)

			-7	70	-9	90	Turbo	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Off	Unit
t _{LVLX}	ALE or AS Pulse Width		15		20			ns
t _{AVLX}	Address Setup Time	(Note 3)	4		6			ns
t _{LXAX}	Address Hold Time	(Note 3)	5		8			ns
t _{AVQV}	Address Valid to Data Valid	(Note 3)		70		90	Add 10**	ns
t _{SLQV}	CS Valid to Data Valid			75		100		ns
	RD to Data Valid	(Note 5)		24		32		ns
t _{RLQV}	RD or PSEN to Data Valid, 80C51XA Mode	(Note 2)		31		38		ns
t _{RHQX}	RD Data Hold Time	(Note 1)	0		0			ns
t _{RLRH}	RD Pulse Width	(Note 1)	27		32			ns
t _{RHQZ}	RD to Data High-Z	(Note 1)		20		25		ns
t _{EHEL}	E Pulse Width		27		32			ns
t _{THEH}	R/\overline{W} Setup Time to Enable		6		10			ns
t _{ELTL}	R/W Hold Time After Enable		0		0			ns
t _{AVPV}	Address Input Valid to Address Output Delay	(Note 4)		20		25		ns

NOTES: 1. $\overline{\text{RD}}$ timing has the same timing as $\overline{\text{DS}}$, $\overline{\text{LDS}}$, $\overline{\text{UDS}}$, and $\overline{\text{PSEN}}$ signals.

2. RD and PSEN have the same timing.

3. Any input used to select an internal PSD4000 function.

4. In multiplexed mode, latched addresses generated from ADIO delay to address output on any Port.

5. $\overline{\text{RD}}$ timing has the same timing as $\overline{\text{DS}}$, $\overline{\text{LDS}}$, and $\overline{\text{UDS}}$ signals.



(5V ± 10% Versions)

Write Timing (5 V ± 10% Versions)

			-:	70	-9	20	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{LVLX}	ALE or AS Pulse Width		15		20		
t _{AVLX}	Address Setup Time	(Note 1)	4		6		ns
t _{LXAX}	Address Hold Time	(Note 1)	5		8		ns
t _{AVWL}	Address Valid to Leading Edge of WR	(Notes 1 and 3)	8		15		ns
t _{SLWL}	$\overline{\text{CS}}$ Valid to Leading Edge of $\overline{\text{WR}}$	(Note 3)	12		15		ns
t _{DVWH}	WR Data Setup Time	(Note 3)	25		35		ns
t _{WHDX}	WR Data Hold Time	(Note 3)	4		5		ns
t _{WLWH}	WR Pulse Width	(Note 3)	25		35		ns
t _{WHAX1}	Trailing Edge of WR to Address Invalid	(Note 3)	6		8		ns
t _{WHAX2}	Trailing Edge of WR to DPLD Address Input Invalid	(Note 3 and 4)	0		0		ns
t _{WHPV}	Trailing Edge of WR to Port Output Valid Using I/O Port Data Register	(Note 3)		27		30	ns
t _{AVPV}	Address Input Valid to Address Output Delay	(Note 2)		20		25	ns

NOTES: 1. Any input used to select an internal PSD4000 function.

2. <u>In multiplexed mode, latched addresses generated from ADIO delay to address output on any Port.</u>

3. WR timing has the same timing as E, DS, LDS, UDS, WRL, and WRH signals.

4. t_{WHAX2} is Address Hold Time for DPLD inputs that are used to generate chip selects for internal PSD memory.

PLD Combinatorial Timing (5 V ± 10%)

			-70		-9	00		Slew	
Symbol	Parameter	Conditions	Min	Max	Min	Max	TURBO OFF	Rate (Note 1)	Unit
t _{PD}	PLD Input Pin/Feedback to PLD Combinatorial Output			22		27	Add 10	Sub 2	ns
t _{ARD}	PLD Array Delay			11		16			ns

NOTE: 1. Fast Slew Rate output available on Port C and F.



(5V ±10% Versions)

Power Down Timing $(5 \lor \pm 10\%)$

			-70		-90		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{LVDV}	ALE Access Time from Power Down			80		90	ns
t _{CLWH}	Maximum Delay from APD Enable to Internal PDN Valid Signal	Using CLKIN Input	15 * t _{CLCL} (µs) (Note 1)			μs	

NOTE: 1. t_{CLCL} is the CLKIN clock period.

$V_{stbyon} Timing (5 \vee \pm 10\%)$

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{BVBH}	Vstby Detection to Vstbyon Output High	(Note 1)		20		μs
t _{BXBL}	V _{stby} Off Detection to V _{stbyon} Output Low	(Note 1)		20		μs

NOTE: 1. Vstbyon is measured at V_{CC} ramp rate of 2 ms.

Reset Pin Timing $(5 \lor \pm 10\%)$

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{NLNH}	Warm RESET Active Low Time (Note 1)		150			ns
t _{OPR}	RESET High to Operational Device				120	ns
t _{NLNH-PO}	Power On Reset Active Low Time		1			ms
t _{NLNH-A}	Warm RESET Active Low Time (Note 2)		25			μs

NOTE: 1. RESET will not abort Flash programming/erase cycles. 2. RESET will abort Flash programming or erase cycle.



(5V ± 10% Versions)

Flash Program, Write and Erase Times $(5 \vee \pm 10\%)$

Symbol	Parameter	Min	Тур	Max	Unit
	Flash Program		8.5		sec
	Flash Bulk Erase (Preprogrammed to 00) (Note 1)		3	30	sec
	Flash Bulk Erase		10		sec
t _{WHQV3}	Sector Erase (Preprogrammed to 00)		1	30	sec
t _{WHQV2}	Sector Erase		2.2		sec
t _{WHQV1}	Word Program		14	1200	μs
	Program/Erase Cycles (Per Sector)	100,000			cycles
t _{WHWLO}	Sector Erase Time-Out		100		μs
t _{Q7VQV}	DQ7 Valid to Output Valid (Data Polling) (Notes 2 and 3)			30	ns

NOTE: 1. Programmed to all zeros before erase.

2. The polling status DQ7 is valid tQ7VQV ns before the data DQ0-7 is valid for reading.

3. DQ7 is DQ15 for Motorola MCU with 16-bit data bus.

ISC Timing $(5 \vee \pm 10\%)$

			-:	70	-9	90	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{ISCCF}	TCK Clock Frequency (except for PLD)	(Note 1)		20		18	MHz
t _{ISCCH}	TCK Clock High Time	(Note 1)	23		26		ns
t _{ISCCL}	TCK Clock Low Time	(Note 1)	23		26		ns
t _{ISCCF-P}	TCK Clock Frequency (for PLD only)	(Note 2)		2		2	MHz
t _{ISCCH-P}	TCK Clock High Time (for PLD only)	(Note 2)	240		240		ns
t _{ISCCL-P}	TCK Clock Low Time (for PLD only)	(Note 2)	240		240		ns
t _{ISCPSU}	ISC Port Set Up Time		6		8		ns
t _{ISCPH}	ISC Port Hold Up Time		5		5		ns
t _{ISCPCO}	ISC Port Clock to Output			21		23	ns
t _{ISCPZV}	ISC Port High-Impedance to Valid Output			21		23	ns
t _{ISCPVZ}	ISC Port Valid Output to High-Impedance			21		23	ns

NOTES: 1. For "non-PLD" programming, erase or in ISC by-pass mode.

2. For program or erase PLD only.



PSD4000 DC Characteristics (3.0 V to 3.6 V Versions) Advance Information

Symbol	Par	ameter	Conditions	Min	Тур	Max	Unit
V _{CC}	Supply Voltage		All Speeds	3.0		3.6	V
V _{IH}	High Level Input Vo	oltage	3.0 V < V _{CC} < 3.6 V	.7 V _{CC}		V _{CC} +.5	V
V _{IL}	Low Level Input Vo	ltage	3.0 V < V _{CC} < 3.6 V	5		0.8	V
V _{IH1}	Reset High Level Ir	nput Voltage	(Note 1)	.8 V _{CC}		V _{CC} +.5	V
V _{IL1}	Reset Low Level In	put Voltage	(Note 1)	5		.2 V _{CC} –.1	V
V _{HYS}	Reset Pin Hysteres	sis		0.3			V
V _{LKO}	V _{CC} Min for Flash E	Erase and Program		1.5		2.2	V
V _{OL}	Output Low Voltage	j	$I_{OL} = 20 \ \mu A, \ V_{CC} = 3.0 \ V$		0.01	0.1	V
VUL		-	I _{OL} = 4 mA, V _{CC} = 3.0 V		0.15	0.45	V
V _{он}	Output High Voltag	e Except Votev On	$I_{OH} = -20 \ \mu A, \ V_{CC} = 3.0 \ V$	2.9	2.99		V
∙он	Output high voltag	e Eveept vSIBY on	I _{OH} = -1 mA, V _{CC} = 3.0 V	2.7	2.8		V
V _{OH1}	Output High Voltag	e V _{STBY} On	I _{OH1} = −1 μA	V _{SBY} - 0.8			V
V _{SBY}	SRAM Standby Vol	Itage		2.0		V _{CC}	V
I _{SBY}	SRAM Standby Cu	rrent (V _{STBY} Pin)	V _{CC} = 0 V		0.5	1	μA
I _{IDLE}	Idle Current (V _{STBY}	Pin)	V _{CC} > V _{SBY}	-0.1		0.1	μA
V _{DF}	SRAM Data Retent	tion Voltage	Only on V _{STBY}	$3.0 \vee$ 0.15 0.45 $s = 3.0 \vee$ 2.9 2.99 $= 3.0 \vee$ 2.7 2.8 $\vee_{SBY} - 0.8$ \vee_{CC} 2.0 \vee_{CC} 0.5 1 -0.1 0.1 2 0.5 -0.1 0.1 2 0.5 -0.1 0.1 2 0.5 -0.1 0.1 0.5 1 -0.1 0.5 0.1 0.1 2 0.5 0.1			V
I _{SB}	Standby Supply Cu for Power Down Mo		CSI >V _{CC} –0.3 V (Notes 2 and 3)		50	100	μΑ
ILI	Input Leakage Curr	rent	$V_{SS} < V_{IN} < V_{CC}$	-1	±.1	1	μA
I _{LO}	Output Leakage Cu	urrent	0.45 < V _{IN} < V _{CC}	-10	±5	10	μA
Io	Output Current		Refer to I_{OL} and I_{OH} in the V_{OL} and V_{OH} row				
			PLD_TURBO = OFF, f = 0 MHz (Note 3)		0		mA
I _{CC} (DC)	Operating	PLD Only	PLD_TURBO = ON, f = 0 MHz		200	400	μΑ/ΡΤ
(Note 5)	Supply Current	FLASH	During FLASH Write/Erase Only		10	25	mA
			Read Only, f = 0 MHz		0	0	mA
		SRAM	f = 0 MHz		0	0	mA
	PLD AC Base				(Note 4)		Figure 27
I _{CC} (AC) (Note 5)	FLASH AC Adder				1.5	2.0	mA/MHz
(/ - /	SRAM AC Adder				0.8	1.5	mA/MHz

NOTES: 1. Reset input has hysteresis. V_{IL1} is valid at or below $.2V_{CC}$ – 1. V_{IH1} is valid at or above $.8V_{CC}$. 2. CSI deselected or internal PD mode is active.

3. PLD is in non-turbo mode and none of the inputs are switching.

4. Refer to Figure 31a for PLD current calculation.

5. $I_0 = 0$ mA.



Microcontroller
Interface -
PSD4000
AC/DCAC Symbols for PLD Timing.Example:tAVLX - Time from Address Valid to ALE Invalid.Signal Letters
Parameters
(3.0 V to 3.6 VA - Address Input
C - CEout Output

- Versions)
- **D** Input Data
- E E Input
- L ALE Input
- N Reset Input or Output
- P Port Signal Output
- **Q** Output Data
- $\mathbf{R} = \overline{WR}, \overline{UDS}, \overline{LDS}, \overline{DS}, IORD, \overline{PSEN}$ Inputs
- S Chip Select Input
- T R/W Input
- W Internal PDN Signal
- B Vstby Output

Signal Behavior

- t Time
- L Logic Level Low or ALE
- H Logic Level High
- V Valid
- X No Longer a Valid Logic Level
- Z Float
- PW Pulse Width



(3.0 V to 3.6 V Versions)

Read Timing (3.0 V to 3.6 V Versions)

			-9	90	- 1	12	Turbo	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Off	Unit
t _{LVLX}	ALE or AS Pulse Width		22		24			ns
t _{AVLX}	Address Setup Time	(Note 3)	7		9			ns
t _{LXAX}	Address Hold Time	(Note 3)	8		10			ns
t _{AVQV}	Address Valid to Data Valid	(Note 3)		90		120	Add 20**	ns
t _{SLQV}	CS Valid to Data Valid			90		120		ns
	RD to Data Valid	(Note 5)		35		35		ns
t _{RLQV}	RD or PSEN to Data Valid, 80C51XA Mode	(Note 2)		45		48		ns
t _{RHQX}	RD Data Hold Time	(Note 1)	0		0			ns
t _{RLRH}	RD Pulse Width	(Note 1)	36		40			ns
t _{RHQZ}	RD to Data High-Z	(Note 1)		38		40		ns
t _{EHEL}	E Pulse Width		38		42			ns
t _{THEH}	R/W Setup Time to Enable		10		16			ns
t _{ELTL}	R/W Hold Time After Enable		0		0			ns
t _{AVPV}	Address Input Valid to Address Output Delay	(Note 4)		30		35		ns

NOTES: 1. \overline{RD} timing has the same timing as \overline{DS} , \overline{LDS} , \overline{UDS} , and \overline{PSEN} signals.

2. RD and PSEN have the same timing for 80C51XA.

3. Any input used to select an internal PSD4135G2V function.

4. In multiplexed mode latched address generated from ADIO delay to address output on any Port.

5. RD timing has the same timing as \overline{DS} , \overline{LDS} , and \overline{UDS} signals.



(3.0 V to 3.6 V Versions)

Write Timing (3.0 V to 3.6 V Versions)

			9	70	-1	2	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{LVLX}	ALE or AS Pulse Width		22		24		
t _{AVLX}	Address Setup Time	(Note 1)	7		9		ns
t _{LXAX}	Address Hold Time	(Note 1)	8		10		ns
t _{AVWL}	Address Valid to Leading Edge of WR	(Notes 1 and 3)	15		18		ns
t _{SLWL}	$\overline{\text{CS}}$ Valid to Leading Edge of $\overline{\text{WR}}$	(Note 3)	15		18		ns
t _{DVWH}	WR Data Setup Time	(Note 3)	40		45		ns
t _{WHDX}	WR Data Hold Time	(Note 3)	5		8		ns
t _{WLWH}	WR Pulse Width	(Note 3)	40		45		ns
t _{WHAX1}	Trailing Edge of \overline{WR} to Address Invalid	(Note 3)	8		10		ns
t _{WHAX2}	Trailing Edge of WR to DPLD Address	(Notes 3 and 4)	0		0		ns
t _{WHPV}	Trailing Edge of WR to Port Output Valid Using I/O Port Data Register	(Note 3)		30		33	ns
t _{AVPV}	Address Input Valid to Address Output Delay	(Note 2)		30		35	ns

NOTES: 1. Any input used to select an internal PSD4000 function.

2. In multiplexed mode, latched addresses generated from ADIO delay to address output on any Port.

3. WR timing has the same timing as E, $\overline{\text{DS}}$, $\overline{\text{LDS}}$, $\overline{\text{UDS}}$, $\overline{\text{WRL}}$, and $\overline{\text{WRH}}$ signals.

4. t_{WHAX2} is Address hold time for DPLD inputs that are used to generate chip selects for internal PSD memory.

PLD Combinatorial Timing $(5 \lor \pm 10\%)$

			-9		-12			Slew	
Symbol	Parameter	Conditions	Min	Max	Min	Max	TURBO OFF	Rate (Note 1)	Unit
t _{PD}	PLD Input Pin/Feedback to PLD Combinatorial Output			42		47	Add 20	Sub 6	ns
t _{ARD}	PLD Array Delay			23		27			ns

NOTE: 1. Fast Slew Rate output available on Port C and F.



(3.0 V to 3.6 V Versions)

Power Down Timing (3.0 V to 3.6 V Versions)

			-9	90	- 1	12	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{LVDV}	ALE Access Time from Power Down			128		135	ns
t _{CLWH}	Maximum Delay from APD Enable to Internal PDN Valid Signal	Using CLKIN Input	15 *	t _{CLCL} (µs) (No	te 1)	μs

NOTE: 1. t_{CLCL} is the CLKIN clock period.

Vstbyon Timing (3.0 V to 3.6 V Versions)

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
t _{BVBH}	V _{stby} Detection to V _{stbyon} Output High	(Note 1)		20		μs
t _{BXBL}	V _{stby} Off Detection to V _{stbyon} Output Low	(Note 1)		20		μs

NOTE: 1. Vstbyon is measured at V_{CC} ramp rate of 2 ms.

Reset Pin Timing (3.0 V to 3.6 V Versions)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{NLNH}	Warm RESET Active Low Time (Note 1)		300			ns
t _{OPR}	RESET High to Operational Device				300	ns
t _{NLNH-PO}	Power On Reset Active Low Time		1			ms
t _{NLNH-A}	Warm RESETActive Low Time (Note 2)		25			μs

NOTE: 1. RESET will not abort Flash programming/erase cycles.

2. RESET will abort Flash programming or erase cycle.



(3.0 V to 3.6 V Versions)

Flash Program, Write and Erase Times (3.0 V to 3.6 V Versions)

Symbol	Parameter	Min	Тур	Max	Unit
	Flash Program		8.5		sec
	Flash Bulk Erase (Preprogrammed to 00) (Note 1)		3	30	sec
	Flash Bulk Erase		10		sec
t _{WHQV3}	Sector Erase (Preprogrammed to 00)		1	30	sec
t _{WHQV2}	Sector Erase		2.2		sec
t _{WHQV1}	Word Program		14	1200	μs
	Program/Erase Cycles (Per Sector)	100,000			cycles
t _{WHWLO}	Sector Erase Time-Out		100		μs
t _{Q7VQV}	DQ7 Valid to Output Valid (Data Polling) (Notes 2 and 3)			30	ns

NOTES: 1. Programmed to all zeros before erase.

2. The polling status DQ7 is valid tQ7VQV ns before the data DQ0-7 is valid for reading.

3. DQ7 is DQ15 for Motorola MCU with 16-bit data bus.

ISC Timing (3.0 V to 3.6 V Versions)

			-9	90	- 1	12	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{ISCCF}	TCK Clock Frequency (except for PLD)	(Note 1)		15		12	MHz
t _{ISCCH}	TCK Clock High Time	(Note 1)	30		40		ns
t _{ISCCL}	TCK Clock Low Time	(Note 1)	30		40		ns
t _{ISCCF-P}	TCK Clock Frequency (for PLD only)	(Note 2)		2		2	MHz
t _{ISCCH-P}	TCK Clock High Time (for PLD only)	(Note 2)	240		240		ns
t _{ISCCL-P}	TCK Clock Low Time (for PLD only)	(Note 2)	240		240		ns
t _{ISCPSU}	ISC Port Set Up Time		11		12		ns
t _{ISCPH}	ISC Port Hold Up Time		5		5		ns
t _{ISCPCO}	ISC Port Clock to Output			26		32	ns
t _{ISCPZV}	ISC Port High-Impedance to Valid Output			26		32	ns
t _{ISCPVZ}	ISC Port Valid Output to High-Impedance			26		32	ns

NOTES: 1. For "non-PLD" programming, erase or in ISC by-pass mode.

2. For program or erase PLD only.



Figure 28. Read Timing

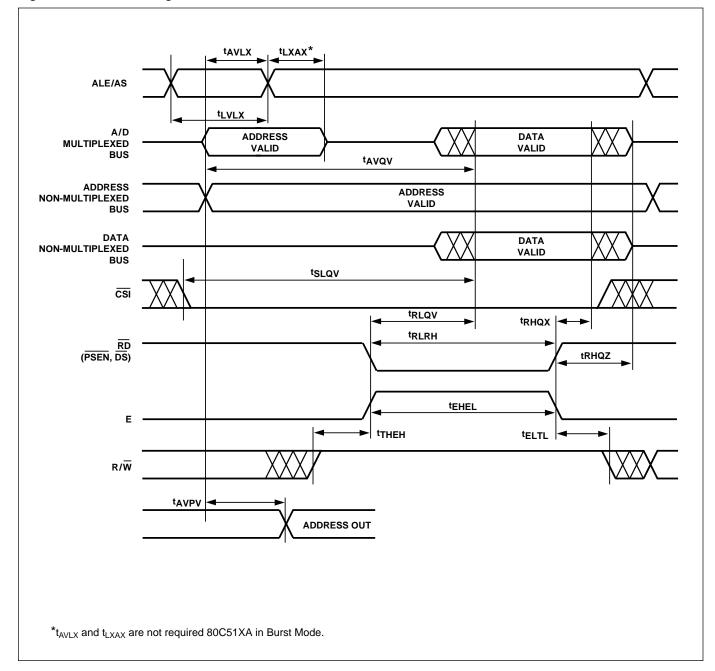




Figure 29. Write Timing

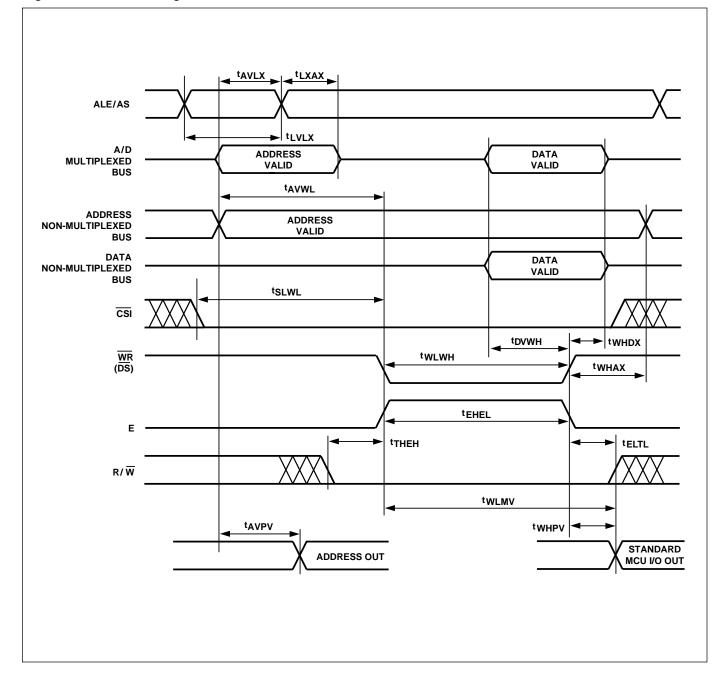
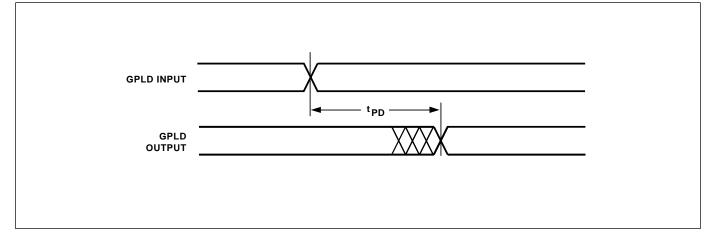
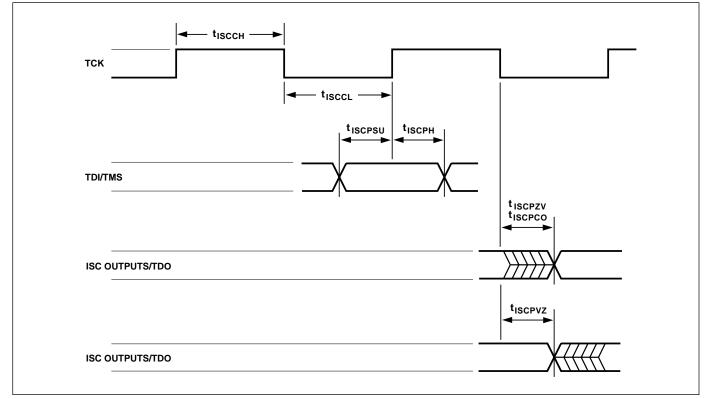




Figure 30. Combinatorial Timing – PLD









Γ

Figure 32. Reset Timing

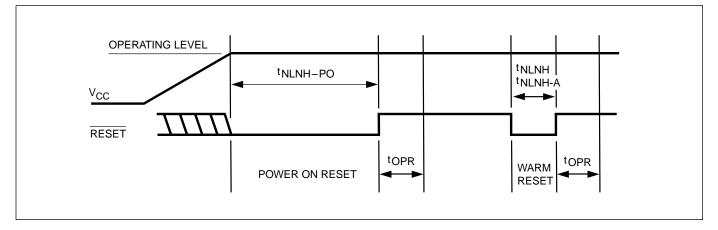


Figure 33. Key to Switching Waveforms

WAVEFORMS	INPUTS	OUTPUTS
	STEADY INPUT	STEADY OUTPUT
	MAY CHANGE FROM HI TO LO	WILL BE CHANGING FROM HI TO LO
	MAY CHANGE FROM LO TO HI	WILL BE CHANGING LO TO HI
	DON'T CARE	CHANGING, STATE UNKNOWN
	OUTPUTS ONLY	CENTER LINE IS TRI-STATE



6

Unit

pF

pF

pF

14.0 $T_A = 25 \text{ °C}, f = 1 \text{ MHz}$ **Pin Capacitance** Parameter¹ Conditions Typical² Symbol Мах Capacitance (for input pins only) $V_{IN} = 0 V$ 4 C_{IN} Capacitance (for input/output pins) $V_{OUT} = 0 V$ 8 12 COUT $V_{PP} = 0 V$ 25 Capacitance (for CNTL2/V_{PP}) 18 CVPP NOTES: 1. These parameters are only sampled and are not 100% tested. 2. Typical values are for $T_A = 25^{\circ}C$ and nominal supply voltages. 15.0 Figure 34. AC Testing 3.0V Input/Output TEST POINT 1.5V Waveform 0V 16.0 2.01 V Figure 35. AC Testing Load Circuit 195 Ω DEVICE UNDER TEST $C_{1} = 30 \text{ pF}$ (INCLUDING

SCOPE AND JIG CAPACITANCE)

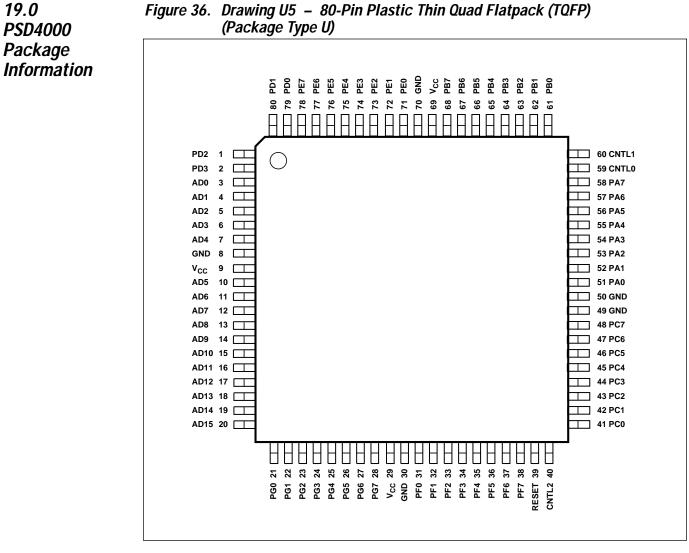
17.0 Upon delivery from Waferscale, the PSD4000 device has all bits in the PLDs and memories in the "1" or high state. The configuration bits are in the "0" or low state. The Programming code, configuration, and PLDs logic are loaded through the procedure of programming.

Information for programming the device is available directly from Waferscale. Please contact your local sales representative. (See the last page.)



18.0 PSD4000		c Thin Quad Flatpack (-	
2304000 Pin	Pin No.	Pin Assignments	Pin No.	Pin Assignments
Assignments	1	PD2	41	PC0
..	2	PD3	42	PC1
	3	AD0	43	PC2
	4	AD1	44	PC3
	5	AD2	45	PC4
	6	AD3	46	PC5
	7	AD4	47	PC6
	8	GND	48	PC7
	9	V _{CC}	49	GND
	10	AD5	50	GND
	11	AD6	51	PA0
	12	AD7	52	PA1
	13	AD8	53	PA2
	14	AD9	54	PA3
	15	AD10	55	PA4
	16	AD11	56	PA5
	17	AD12	57	PA6
	18	AD13	58	PA7
	19	AD14	59	CNTL0
	20	AD15	60	CNTL1
	21	PG0	61	PB0
	22	PG1	62	PB1
	23	PG2	63	PB2
	24	PG3	64	PB3
	25	PG4	65	PB4
	26	PG5	66	PB5
	27	PG6	67	PB6
	28	PG7	68	PB7
	29	V _{CC}	69	V _{CC}
	30	GND	70	GND
	31	PF0	71	PE0
	32	PF1	72	PE1
	33	PF2	73	PE2
	34	PF3	74	PE3
	35	PF4	75	PE4
	36	PF5	76	PE5
	37	PF6	77	PE6
	38	PF7	78	PE7
	39	RESET	79	PD0
	40	CNTL2	80	PD1





usi



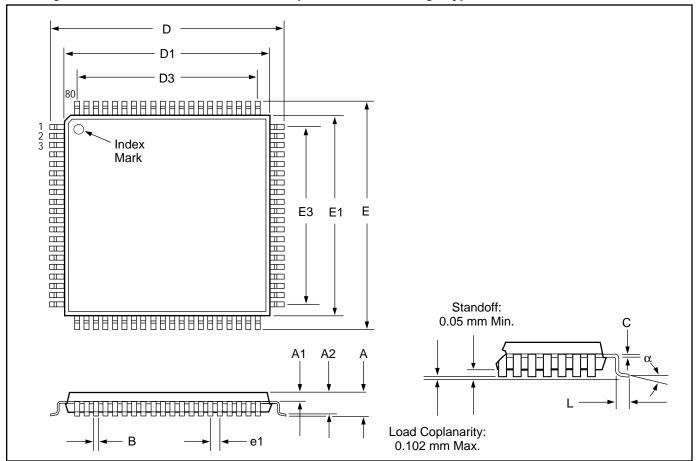


Figure 36A. Drawing U5 – 80-Pin Plastic Thin Quad Flatpack (TQFP) (Package Type U)

Family: Plastic Thin Quad Flatpack (TQFP)

		Millimeters			Inches	
Symbol	Min	Max	Notes	Min	Мах	Notes
α	0°	7°		0°	8°	
А	-	1.20		-	0.047	
A2	0.95	1.05		0.037	0.041	
В	0.17	0.27	Reference	0.007	0.011	
С		0.20			0.008	
D	13.95	14.05		0.512	0.551	
D1	11.95	12.05		0.433	0.472	
D3	9	.5	Reference	0.3	374	Reference
Е	13.95	14.05		0.512	0.551	
E1	11.95	12.05		0.433	0.472	
E3	9	.5	Reference	0.3	374	Reference
e1	0.	50	Reference	0.0)19	Reference
L	0.45	0.75		0.018	0.030	
Ν	8	60		8	60	



Selector Guide – PSD4(Guide -	- PSD	4000	000 Series															
Part # MCU	MCU		PLD	PLDs/Decoders	ders		0/1		Memory	ory				ot	Other			Soft	Software
ъ	Data	Inputs	_	nput Macrocells	s		Ports	Ports Flash Program Store	ogram Sti	ore		ISP vi	ISP via JTAG					PSDsoft	
Volts	Path			Output I	Output Macrocells	lls			2nd Flash Array	th Array			IAP via MCU	MCU				Express	
					Outputs					EEPROM	_		Ň	Zero Power	wer				PSDsoft
						Page					SRAM			<u> </u>	Per. Mode	de		I	2000
						Reg.					w/BB				Se	Security		1	
																PMU	5		
																	APD		
												╡	┨	┨	+				
PSD4135G2	16	57	I	Ι	24	8-bit	52	4096Kb 256Kb	256Kb	I	64Kb	×	×	×	× -	X X	×	Х	×
PSD4235G2 16	16	57	24	16	24	8-bit	52	52 4096Kb 256Kb	256Kb	I	64Kb X X X	×	×		×	× ×	×	×	

W.Si-

PSD4000 Series

21.0 Part Number Construction

PART UMBER P S D 42 1 3 F 2 - A - 1 5 J PSD BRAND NAME PSD = Standard Low Power Device PSD = Standard Low Power Device TEMP RANGE "Blank" = 0°C to +70°C (Commercial I = -0°C to +70°C (Industrial) FAMILY/SERIES 8 = Flash PSD for 8-bit MUCs (with simple PLD) PACKAGE TYPE J = PQFP B81 = BGA PACKAGE TYPE J = PQFP B81 = BGA SRAM SIZE 0 = 0Kb 1 = 16Kb 2 = 232kb 3 = 64kb SPEED - 70 = 70ns 9 = 90ns - 12 = 120ns - 15 = 150ns - 20 = 200ns SPEED - 70 = 70ns - 90 = 90ns - 12 = 120ns - 15 = 150ns - 20 = 200ns WM SIZE 1 = 256kb 2 = 21/0 G = 52 I/O SPEED - 70 = 70rs - 8 = Rev. A - 8 = Rev. B - C = Rev. C Visite 1 = EERROM, 256kb 2 = FLASH, 256kb 2 = FLASH, 256kb 2 = FLASH, 256kb 2 = No 2nd Array Second Contraction Second Contraction	ARACTER # 1 2	ł	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18 19
PSD = Standard Low Power Device FAMILY/SERIES 8 = Flash PSD for 8-bit MUCs (with simple PLD) 41 = Flash PSD for 8-bit MUCs (with simple PLD) 42 = Flash PSD for 16-bit MUCs (with Simple PLD) 42 = Flash PSD for 16-bit MUCs (with Simple PLD) 42 = Flash PSD for 16-bit MUCs 2 = 512kb 3 = 64kb NVM SIZE 1 = 256kb 2 = 512kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O			5	D	4	2	1	3	F	2		-	A	-	1	5	J	
8 = Flash PSD for 8-bit MCUs 9 = Flash PSD for 8-bit MUCs (with simple PLD) 41 = Flash PSD for 16-bit MUCs (with PPLD) 42 = Flash PSD for 16-bit MUCs (with CPLD) SRAM SIZE 0 = 0Kb 1 = 16Kb 2 = 32Kb 3 = 64Kb NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VOCOUNT & OTHER F = 27 I/O 5 = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb	PSD = Standard Lo																	"Blank" = 0°C to +70°C (Commercial
9 = Flash PSD for 8-bit MUCs (with simple PLD) 41 = Flash PSD for 16-bit MUCs (with simple PLD) 42 = Flash PSD for 16-bit MUCs (with CPLD) SRAM SIZE 0 = 0Kb 1 = 16Kb 2 = 32Kb 3 = 64Kb NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb 2ND NVM TYPE, SIZE 8 CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb		-bi	t M	CUs														
41 = Flash PSD for 16-bit MUCs (with simple PLD) 42 = Flash PSD for 16-bit MUCs (with CPLD) SRAM SIZE 0 = 0Kb 1 = 16Kb 2 = 32Kb 3 = 64kb NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 <i>VO</i> G = 52 <i>I/O</i> 2ND NVM TYPE, SIZE a CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb		l-bi	t M	UCs	;													M = PQFP
(with CPLD) SRAM SIZE 0 = 0Kb 1 = 16Kb 2 = 32Kb 3 = 64Kb NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb 2 = FLASH, 256Kb		16	-bit	MU	Cs													D01 = D0A
SRAM SIZE - 70 = 70ns 0 = 0Kb - 90 = 90ns 1 = 16Kb - 12 = 120ns 2 = 32Kb - 15 = 150ns 3 = 64Kb - 20 = 200ns REVISION ************************************		16	-bit	MU	Cs										SPFI	-D		
0 = 0Kb 1 = 16Kb 2 = 32Kb 3 = 64Kb NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb	SDAM SIZE														- 70 -	= 701		
2 = 32Kb 3 = 64Kb NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE a CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb																		
3 = 64Kb NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb																		
NVM SIZE 1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb															- 20 =	= 200	Jns	
1 = 256Kb 2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb	NVM SIZE							1										
2 = 512Kb 3 = 1Mb 4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb	1 = 256Kb															ev.		
4 = 2Mb 5 = 4Mb VO COUNT & OTHER F = 27 I/O G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb																		
VO COUNT & OTHER F = 27 I/O "blank" = 5 Volt G = 52 I/O V = 3.0 Volt 2ND NVM TYPE, SIZE * CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb													- C =	= Re	v. C			
VO COUNT & OTHER "blank" = 5 Volt F = 27 I/O "blank" = 5 Volt G = 52 I/O V = 3.0 Volt 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb	5 = 4Mb																	
G = 52 I/O 2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb	I/O COUNT & OTH	ER							-									
2ND NVM TYPE, SIZE & CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb												V =	= 3.0	Volt				
& CONFIGURATION 1 = EEPROM, 256Kb 2 = FLASH, 256Kb	G = 52 I/O																	
1 = EEPROM, 256Kb 2 = FLASH, 256Kb																		
3 = NO ZNO ANAY																		
	s = 100 200 Array																	

22.0 Ordering Information



23.0 Temporary Exceptions to Specification

The following information describes exceptions to specifications contained in this data sheet. These exceptions will be corrected in future releases of PSD4135G2 and will be identified by date code.

1. The Battery Backup SRAM Feature

Normal Operation – The PSD SRAM can be backed-up by an external battery in the event of a system power down or failure. This feature is enabled in PSDsoft and by connecting the battery to the Vstby pin on Port E (PE6). Automatic power switchover will occur when the system voltage level (V_{CC}) drops below the battery voltage.

Discrepancy – This feature is not functional, may cause latch up if battery is connected to pin PE6. Pin PE6 can be configured to perform other I/O functions. Do not connect the battery until the problem is fixed. The "Vbaton" function on pin PE7 is not available since the battery is not connected to the PSD.





Document Revisions

Date	Revision Reason	Data Sheet Changes
1 May 00	PSD4135G2 Initial release	_

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